



Product Brochure

A Global Provider of Embedded SOMs & Solutions

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Company Profile

MYIR Electronics Limited (MYIR for short), established in 2011, is a global provider of embedded System-On-Modules (SOMs) and comprehensive solutions based on various architectures such as ARM, FPGA, RISC-V, and AI. We cater to customers' needs for large-scale production, offering customized design, industry-specific application solutions, and one-stop OEM services.

MYIR, recognized as a national high-tech enterprise, is also listed among the "Specialized and Special new" Enterprises in Shenzhen, China. Our core belief is that "Our success stems from our customers' success" and embraces the philosophy of "Make Your Idea Real, then My Idea Realizing!"



ISO 14001



ISO 9001



ISO 13485

15+ years
Industry Expertise

45+ %
R&D Personnel

7,000+ M²
R&D and
Manufacturing Base

150+
Patents & Honors

30,000+
Worldwide Customers

History

2011-2012

- Shenzhen Headquarter Established
- Beijing Office Established
- Shanghai Office Established
- Became ARM Approved Partner
- Became Xilinx Design Partner

2013-2017

- Became TI Design Network Partner
- Became NXP Approved Partner
- Became IDH Partner of AVNET
- Wuhan R&D Center Established
- Head Office Moved to Yunli Smart Park

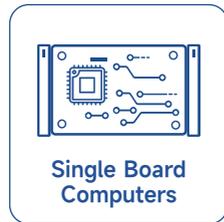
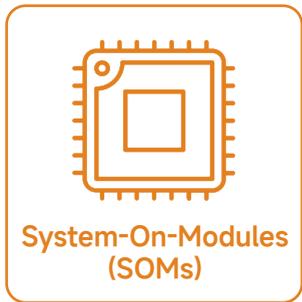
2018-2021

- SMT Factory Established in Guanlan, Shenzhen
- Became ST Authorized Partner
- Became SemiDrive Design Partner
- Mouser Became Distributor
- Digi-key Became Distributor
- Qualified as National High-tech Enterprise
- ISO9001 certificated
- ISO14001 certificated

2022-2025

- Became IDH Partner of Renesas
- Became Allwinner Design Partner
- Became Partner of Rockchip
- Became Partner of Nuvoton
- Honored with The Partner Award from ST
- Awarded with "Shenzhen Specialized and Special New Enterprise"
- Attended embeddworld2025 in Nuremberg, Germany

■ Main Business



■ Application Fields



Corporate Culture



Mission

Laying the foundation for digital, intelligent, and networked embedded products to enable intelligent manufacturing and smart living.



Vision

To become the most trusted provider of embedded SOMs for industrial customers worldwide.



Values

Co-creation, win-win collaboration, and sharing, aiming to create maximum value for customers.

Information Management Platform

MYIR has developed a comprehensive range of professional and sophisticated enterprise-level information management platforms. These platforms enable comprehensive digital management across various dimensions, including material supply chain, product research and development, customer management, project management, employee management, production management, and more. Through these platforms, MYIR aims to achieve business digitization, management visualization, and intelligent production.



Enterprise Management

ERP System



Customer Management

CRM System



Supplier Management

SRM System



Product Management

PLM System, DFX System



Production Management

MES System, iDAS Electrostatic Monitoring System, WMS Intelligent Storage System

Business Philosophy



Leading Technology

Continuously engaging in technological innovation to provide customers with cutting-edge technologies and products.



Professional Service

Systematically establishing a customer service framework and offering comprehensive technical support throughout the entire sales cycle, from pre-sales to post-sales.



Delivery Commitment

Guaranteeing a product lifecycle of no less than 10 years.



Quality Assurance

The ISO management system runs through the entire process, from material selection to R&D, product testing, production, and shipment.

Qualifications and Honors



National High-Tech Enterprise



Shenzhen Specialized and Special New Enterprise



ISO9001



ISO14001



IDH Partner of Renesas



Partner Award from ST for MYIR



Quality Supplier of XJ Power Co., Ltd.



Quality Supplier of NARI Group



CE Certification



RoHS Certification



Software Copyright



Certificate of Utility Model Patent



Certificate of Invention Patent



Certificates of the Registration for Integrated Circuit Layout Designs

Strategic Partners



Our Clients (Part)



R&D Capabilities

MYIR has established R&D centers in both Shenzhen and Wuhan, and boasts a senior technical R&D team. Approximately 45% of our personnel are dedicated to R&D, and all of them possess a bachelor's degree or higher. The core and backbone members of our R&D team possess extensive experience in the embedded industry, having accumulated more than 10 years of professional expertise in the field. They are equipped with cutting-edge design concepts and practices specially tailored for high-volume product applications. Our products exhibit industry-leading innovation, reliability, and stability, and we have filed for numerous patents, copyrights, and various certifications, exceeding a total of 100.



Excellence, Scientific, and Systematic R&D Management

 **Complete R&D Management**
Adopting the IPD process management concept, combined with modern information system management tools

 Project Management

 Task Management

 Defect Management

 Review Management

 Design Documentation

 Code Management

 Knowledge and Experience Management

 **Design Capability Optimization**
Establish complete and unified key design node control

 Test Example

 Schematic/PCB CheckList

 Standard Circuit Library

 DFX Management

 High-speed Signal Design and Simulation

 Material AVL Preferred Library

Technology and Skills

Hardware Development

- Standard Component Library
- Standard Circuit Diagram
- Complete Schematic (PCB CheckList)
- FMEA Analysis
- SI Simulation Design

Software Development

- Multiple OS Development Capabilities
Linux  |  android |  RTOS
- Kernel Porting and Driver Development Capabilities
- System Optimization Capabilities
(boot time, real-time performance, multi-system backup, OTA, security, etc.)
- System Customization Capabilities
Conform to Industrial and Power scenarios
- Protocol Development and Application Development Capabilities

Testing Capability

The MYIR R&D and testing team adheres to a scientific, rigorous, objective and fair attitude, relying on a comprehensive testing system and professional, extensive testing experience. All products are strictly tested in accordance with relevant national standards, industry standards, and company standards, ensuring that all the product has long-term stability, reliability, mass production capability, and data traceability.

Standards Range

- Corresponding chip data manual

Main Evaluation Items

Power Test

- ✓ Ground Impedance Test
- ✓ Ripple Test
- ✓ Up-down Waveform Test
- ✓ Power On/Off Timing Test
- ✓ Power Consumption Test
- ✓ Power Noise Test

Signal Test

- ✓ I2C Test
- ✓ I2S Test
- ✓ SDIO Test
- ✓ Clock Test
- ✓ Ethernet Test
- ✓ UART Test
- ✓ CAN Test
- ✓ RS232/RS485 Test

Signal Test

Standards Range

- EN55032
- IEC61000-4
- NB/T33008.1
- GB/T 17626

Main Evaluation Items

EMI: Electromagnetic Interference

- ✓ RE: Radiation Emission
- ✓ CE: Conducted Emissions
- ✓ Harmonics: Harmonic Current
- ✓ Flicker: Flashing

EMS: Electromagnetic Sensitivity

- ✓ RS: Radiation Immunity
- ✓ CS: Conducted Immunity
- ✓ ESD: Electrostatic Immunity
- ✓ Surge: Surge Immunity
- ✓ EFT/B: Electric Fast Transient Pulse Group
- ✓ PMS: Power Frequency Magnetic Field Anti-interference Degree
- ✓ Dips: Voltage Drop/Short Interruption

EMC Test

Standards Range

- EN 55032: 2015
- EN 55035: 2017
- IEC62321
- EN 61000-3-3: 2013
- EN IEC 61000-3-2: 2019

Main Evaluation Items

- ✓ CE Certification
- ✓ RoHS Certification



Certification

Standards Range

- GB/T 2423.2-2008
- GB/T 2423.22-2012
- GB/T 2423.5-2019
- GB/T 2423.8-1995
- GB/T 2423.10-2019
- GB/T 19056-2012
- GB/T 2423.17-2008
- GB/T 2423.10-2019

Main Evaluation Items



Reliability Test

Technical Services

MYIR is customer-oriented, and provides comprehensive technical support and services for various issues encountered by customers during the processes of project selection, project approval, project development, product testing, small-batch trial production, and mass production. The company's frontline engineering team assists customers in solving technical problems through various channels such as online communication, telephone, email, remote video conferencing, and on-site services, and provides abundant learning materials. MYIR is committed to accelerating the customer's development process, reducing the customer's development costs, ensuring the quality of the customer's products, and enhancing the competitiveness of the customer's products in the market.

Pre-sales Service

1 Communication and Requirement Analysis
The technical service team actively and comprehensively participates in analyzing and understanding customer requirements.

4 Prototype Verification
We ensure the feasibility and stability of the system design for the selected platform.

2 Consultative Product Selection Guidance
Our professional team recommends the most suitable SOM optimized for performance, functionality, and cost-effectiveness.

5 Project Technical Risk Assessment
We identify potential risks, propose effective solutions, and formulate countermeasures.

3 Software and Hardware Framework Construction
We ensure that the overall software and hardware system design aligns with and fulfills the customer's specific requirements.

In-sales Service

1 Developer Resources Download
Provide detailed documentation and software packages for products.

4 Assist with Driver Development
Ensure compatibility between hardware and software, and verify the functionality and performance of underlying drivers.

7 Material Selection Guidance
Provide suggestions on quality, performance, and pricing to enhance product competitiveness.

10 R&D Sampling Service
Provide one-stop sampling services and reports, analyze potential issues, and provide improvement suggestions.

2 Schematic and PCB Design Guidance
Ensure that the circuit design layout is reasonable and meets system performance and stability requirements.

5 Assist with Middleware Porting
Ensure the normal operation and functional integrity of the system.

8 Test Plan Guidance
Ensure the project meets quality standards before launch and guarantee product stability.

3 Schematic and PCB Review
Avoid potential circuit board design issues and defects.

6 Assist with System Optimization and Cropping
Improve system performance and stability while reducing resource consumption.

9 Production Process Guidance
Provide production process guidance documents as a reference to ensure product efficiency and quality.

After-sales Service

Technical Support
Respond to customer queries in a timely manner, primarily providing support through emails, phone calls, or online meetings.

Knowledge Sharing
Aid customers in enhancing their understanding of product usage through articles, documentation and videos.

Problem Recording and Organization
Maintain separate records for each customer issue to track the root cause and implement continuous improvement measures.

Output 8D report
The report encompasses a comprehensive analysis, including problem description, root cause analysis, corrective actions, preventive measures, and improvement suggestions.

Warranty
Offer product repair and exchange services. MYIR's production system ensures batch traceability at both the product and material levels, facilitating problem identification, analysis, resolution, as well as the provision of analysis reports and usage suggestions.

Quality Assurance

MYiR has implemented a series of inspection steps, including incoming inspection of materials, pre-assembly baking, solder paste printing inspection, online AOI, first article inspection, spot X-RAY inspection, IPQC patrol inspection, and QA outgoing inspection. We also conduct comprehensive real-time electrostatic protection monitoring. By adhering to the ISO9001 quality management system, we ensure a high product qualification rate for all outgoing products.



Systematic Warehouse Management

The warehouse uses X-ray automatic component counting machines and AI-enabled intelligent sensing shelves. For the electronic components warehouse, it maintains a controlled temperature and humidity, incorporates anti-static measures, and strictly adheres to a first-in-first-out inventory management protocol. It supports the issuance of materials for multiple work orders, enables real-time inventory tracking, prevents material loss and errors, seamlessly integrates with MES and ERP systems, and ensures traceability throughout the entire process of usage and management.



WMS Intelligent Warehousing System

Intelligent shelves, combined with a smart warehouse system, achieve zero material error.



Constant Temperature and Constant Humidity, Ensuring Safety

Integrated circuits and electronic components are stored in warehouses and cabinets maintained at constant temperature and humidity to ensure the effectiveness and reliability of materials.



A Complete Supply Chain System

We have a senior supply chain management team with over 10 years of industry experience. We offer comprehensive BOM material supply, component selection, and substitute recommendation services. With professional BOM engineers and strict, standardized IQC incoming material inspection standards, as well as original genuine product guarantees sourced from original manufacturers and primary agents, we ensure that we provide our customers with short delivery times, high-quality, and low-price component guarantees.



1,000+ Original Manufacturers and Agent Cooperation Partners (including some of them)



Production Capacity

MYIR has a 5,000-square-meter smart SMT factory, equipped with a Class 100,000 cleanroom and multiple SMT production lines. Leveraging advanced production equipment, sophisticated management systems, stringent quality control processes, a comprehensive supply chain network, and robust engineering support, we guarantee product quality throughout the entire process, from raw material sourcing to production and ultimately shipping. Our factory possesses a surface mount capability of over 5 million points per day, and all production processes adhere strictly to RoHS and REACH standards.

Complete Automated Production Equipment

Equipped with Panasonic imported high-speed dual-track SMT line, our factory has fully automatic solder paste printer, nitrogen reflow oven, wave soldering machine, AOI, SPI and X-RAY inspection machines, intelligent first article inspection instrument, intelligent solder paste management cabinet, automatic PCB router machine, conformal coating machine, laser engraving machine, BGA rework stations, and other equipment. It is also supported by MES intelligent management system, intelligent warehousing system, ERP system, and static electricity management system.



Automatic Solder Paste Printer



Automatic Solder Paste Inspection Machine (3D SPI)



NPM-D3A SMT Machine



NPM-TT2 SMT Machine



Online AOI



Automatic Coating Production Line

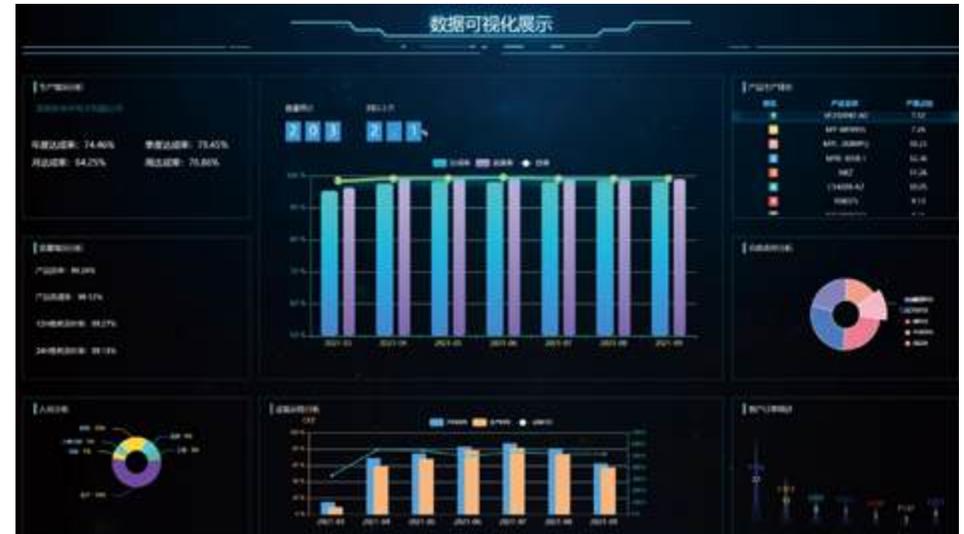
● Excellent Production Environment Conditions

The production workshop equipment and assembly line stations are equipped with LoRa electrostatic monitoring nodes. If the electrostatic levels exceed the standard, audible and visual alarms will be triggered. The real-time data collected by the gateway will be transmitted to the data backend. Overall electrostatic data from the workshop can be dynamically displayed on a large screen in multiple dimensions.

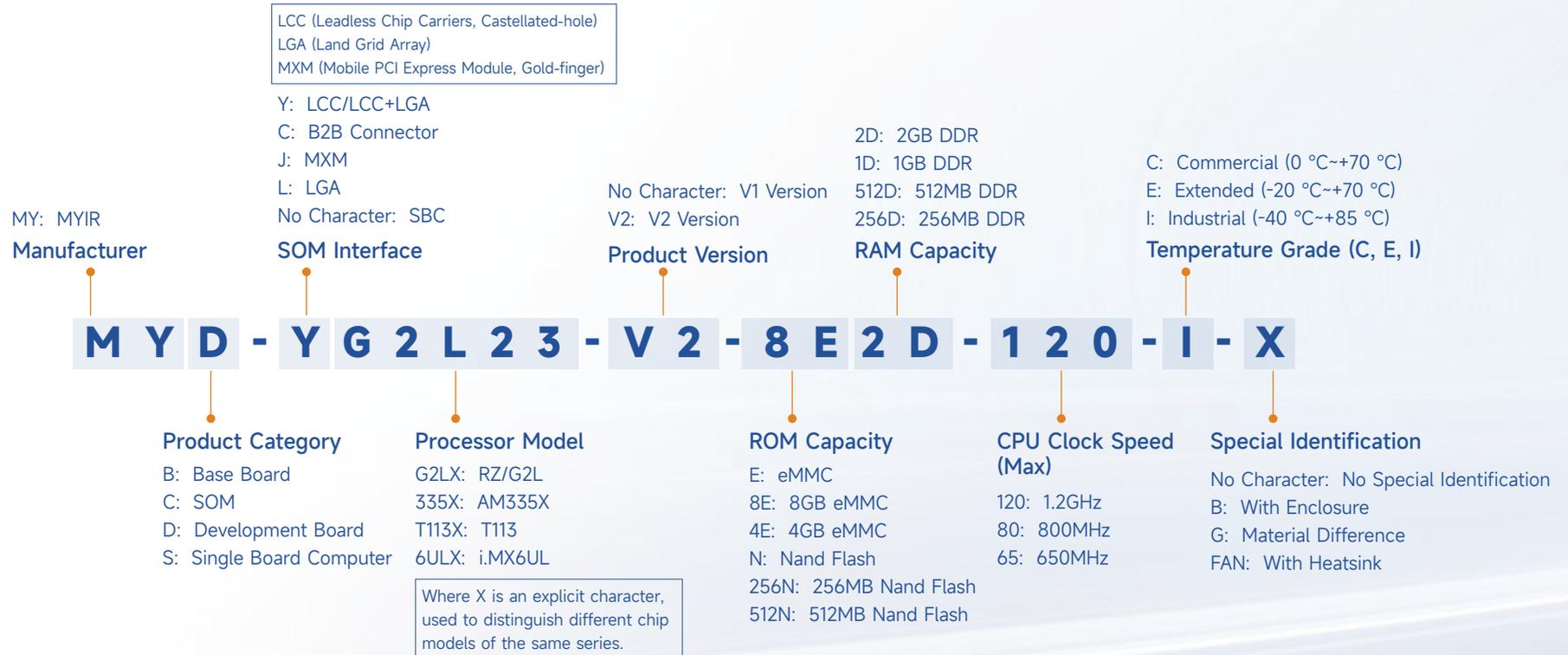


● Integrated Manufacturing Information Management System

An industry-leading integrated manufacturing information management system (MES) that enables seamless integration with ERP, WMS, SRM and other systems, improving the real-time nature and transparency of factory management, as well as the level of full-process traceability and error prevention control for products.



Naming Convention



SOM Selection Table

CPU Vendor	ST		NXP		AMD XILINX		TEXAS INSTRUMENTS	
Performance								
Entry-level A7/A8/A9/ A55/FPGA 1-2 Cores	MYC-YF13X ^{P20} ST STM32MP135 A7@1.0GHz 2×1000M ETH, 8×UART, Parallel CSI 2×CAN FD, Parallel LCD	MYC-Y6ULX-V2 ^{P24} NXP i.MX6UL/i.MX6ULL A7@528MHz 2×100M ETH, 2×CAN, 8×UART Parallel LCD, Parallel CSI	MYC-J7A100T ^{P31} AMD-Xilinx Artix 7A100T FPGA: 101K 2×1000M ETH, HDMI, UART Camera, 2×SFP, PCIE2.0	MYC-C335X-V4 ^{P37} TI AM335X A8@1.0GHz 2×1000M ETH, 2×CAN, 6×UART 3D GPU, PRU, Parallel LCD	MYC-J335X-V2 ^{P39} TI AM335X A8@1.0GHz 2×1000M ETH, 2×CAN, 6×UART 3D GPU, PRU, Parallel LCD			
	MYC-YA15XC-T ^{P21} ST STM32MP151 A7@650MHz+M4@209MHz 1000M ETH, 8×UART Parallel LCD, Parallel CSI	MYC-LMX91 ^{P25} NXP i.MX 91 A55@1.4GHz 2×RMII, 2×CAN FD, 8×UART RGB, Parallel CSI	MYC-C/Y7Z010/20-V2 ^{P32} AMD-Xilinx XC7Z010/20 ARM: 2×A9@667MHz/766MHz, FPGA: 28K/ 85K 1000M ETH, LCD, USB2.0, CAN UART	MYC-Y335X-V2 ^{P38} TI AM335X A8@1.0GHz 2×1000M ETH, 2×CAN, 6×UART 3D GPU, PRU, Parallel LCD	MYC-C335X-GW ^{P40} TI AM335X A8@1.0GHz 2×1000M ETH, 2×CAN, 6×UART 3D GPU, PRU, Parallel LCD			
	MYC-YA157C-V3 ^{P22} ST STM32MP157 2×A7@650MHz+M4@209MHz 1000M ETH, 8×UART, MIPI DSI 2×CAN FD, 3D GPU		MYC-C7Z015 ^{P34} AMD-Xilinx XC7Z015 ARM: 2×A9@766MHz FPGA: 74K 1000M ETH, LCD, USB2.0, CAN UART, PCIE2.0, SFP		MYC-C437X-V2 ^{P41} TI AM437X A9@1.0GHz 2×1000M ETH, 2×CAN, 6×UART 3D GPU, PRU, Parallel LCD			
Mid-range A35/A53/A55 2-4 Cores	MYC-LD25X ^{P23} ST STM32MP257 2×A35@1.5GHz+M33@400MHz 3×1000M ETH, 4×USART, MIPI DSI, 5×UART, 3×CAN FD, Parallel RGB	MYC-LMX9X ^{P26} NXP i.MX93 2×A55@1.7GHz+M33@250MHz 2×1000M ETH, 2×CAN FD, 8×UART LVDS, MIPI DSI, MIPI CSI			MYC-YM62X ^{P42} TI AM62X 1/2/4×A53@1.4GHz+M4F@400MHz 2×1000M ETH, 3×CAN FD, 9×UART 3D GPU, PRU, GPMC, LVDS			
		MYC-C8MMX-V2 ^{P27} NXP i.MX 8M Mini 4×A53@1.8GHz+M4@400MHz 1×1000M ETH, 4×UART, 1×PCIE2.0 MIPI DSI, MIPI CSI, 3D GPU, VPU						
High-end A53/A55/A72 2-8 Cores		MYC-JX8MPQ ^{P28} NXP i.MX 8M Plus 4×A53@1.8GHz+M7@800MHz 2×1000M ETH, 2×CAN FD, PCIE2.0, 2×USB3.0, NPU, MIPI DSI, HDMI	MYC-CZU3EG/4EV/5EV-V2 ^{P35} AMD-Xilinx XZU3EG/4EV/5EV ARM: 4×A53@1200MHz+2×R5@600MHz FPGA: 154K(3EG)/192K(4EV)/256K(5EV) 1000M ETH, CAN, LCD, USB3.0 FMC, DP, SATA3.0, UART, PCIE2.0					
		MYC-J1028X ^{P29} NXP LS1028A 2×A72@1.5GHz 2×1000M ETH, DP1.3/eDP1.4, SATA 3.0 2×USB3.0, 2×PCIE3.0, 4×TSN Switch	MYC-CZU3EG-V3 ^{P36} AMD-Xilinx Zynq UltraScale+ ZU3EG ARM: 4×A53@1200MHz+2×R5F@600MHz FPGA: 154K(3EG) 1000M ETH, CAN, LCD, USB3.0 FMC, DP, SATA3.1, UART, PCIE2.0					
		MYC-JX8MMA7 ^{P30} NXP i.MX 8M Mini+AMD Artix 7 ARM: 4×A53@1.8GHz+M4@400MHz, FPGA: 23K 1000M ETH, 2×USB2.0, 4×UART, 3×SPI, MIPI DSI, MIPI CSI						

SOM Selection Table

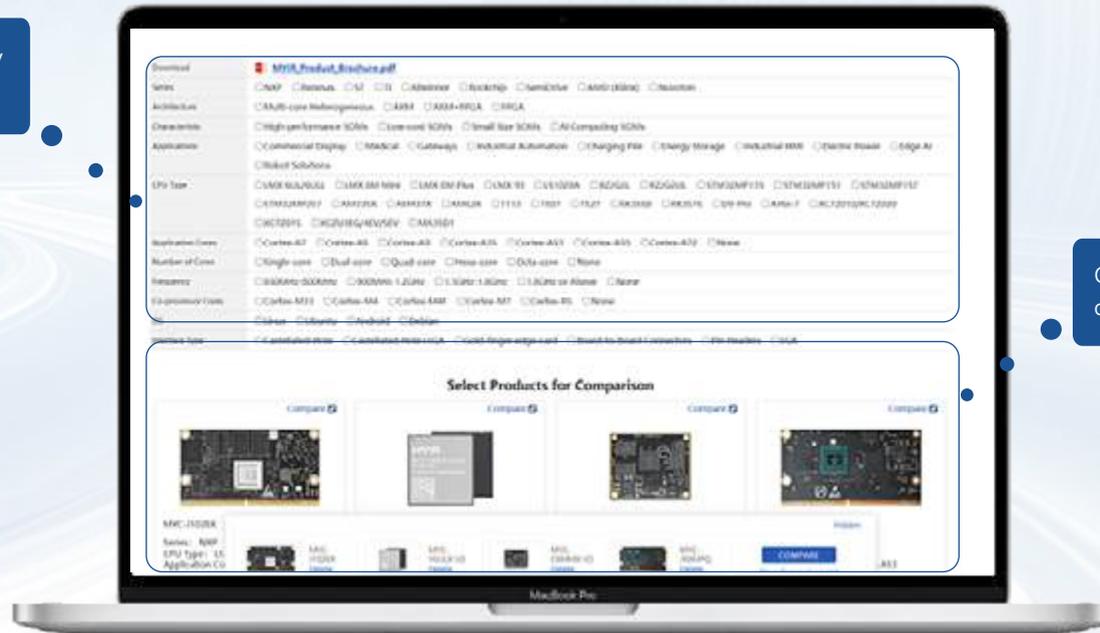
Performance	CPU Vendor					
	Entry-level A7/A8/A9/ A55/FPGA 1-3 Cores		MYC-YG2UL ^{P43} Renesas RZ/G2UL A55@1.0GHz+M33@200MHz 2x1000M ETH, 2xUSB2.0, 1xMIPI CSI 7xUART, 2xCAN FD, 3xSPI, 1xRGB	MYC-YT113i ^{P45} Allwinner T113-i 2xA7@1.2GHz 1000M ETH, 6xUART, Parallel CSI MIPI DSI, RGB, 2xLVDS, 2xCAN		
			MYC-YT113X ^{P46} Allwinner T113-S3 2xA7@1.2GHz 1000M ETH, 6xUART, Parallel CSI MIPI DSI, RGB, 2xLVDS, 2xCAN			
						MYC-YR3506 ^{P52} Rockchip RK3506 3xA7@1.5GHz+M0@200MHz 2x100M ETH, 6xUART, 3xSPI, 2xCAN 2xUSB2.0, 2xMIPI CSI, 12xPWM, 3xI2C
Mid-range A35/A53/A55 2-4 Cores		MYC-YG2LX ^{P44} Renesas RZ/G2L 2xA55@1.2GHz+M33@200MHz 2x1000M ETH, 2xUSB2.0, 7xUART, 2xCAN FD, 3D GPU, VPU, MIPI DSI	MYC-LT536 ^{P47} Allwinner T536 4xA55@1.6GHz+RISCV@600MHz 2x1000M ETH, 17xUART, 4xI2S 4xUSB2.0, Localbus, 4xCAN FD		MYC-LMA35 ^{P51} Nuvoton MA35D1 2xA35@800MHz+M4@180MHz 2x1000M ETH, 4xCAN FD, 17xUART 16bit EBI, 24bit RGB, 2xUSB2.0	MYC-YR3562 ^{P53} Rockchip RK3562 4xA53@2.0GHz+MCU@200MHz 1000M ETH, 2x100M ETH, 10xUART 16xPWM, USB2.0, 2xCAN, SDIO
			MYC-YT507H ^{P48} Allwinner T507-H 4xA53@1.5GHz 1000M ETH, 1xFE, 6xUART 4xUSB2.0, 2xLVDS, RGB, 3D GPU			MYC-LR3568 ^{P54} Rockchip RK3568 4xA55@2.0GHz 2x1000M ETH, 2xHDMI, 2xMIPI CSI eDP1.3, 4xUSB, 2xPCIe3.0, SATA3.0
			MYC-LT527 ^{P49} Allwinner T527 8xA55@1.8GHz+RISC-V@200MHz 2x1000M ETH, HDMI, MIPI DSI/CSI 3xUSB, 2xCAN, 10xUART, 4xSPI	MYC-JD9360 ^{P50} SemiDrive D9360 6xA55@1.6GHz+R5@800MHz 2x1000M ETH, 2xUSB3.0, 2xPCIe3.0 4xCAN FD, 8xSPI, 12xI2C, 8xPWM		
High-end A53/A55/A72 2-8 Cores			4xA55@1.6GHz+RISCV@600MHz			

MYiR Products Selection Site

<https://en.myir.cn/Select.html>



Filter product categories to quickly locate specific category products.



Check 2 to 4 SOMs to compare specific parameters.

Advantages of MYIR's System-On-Modules



Innovative Design

▶ LCC/LGA Packaging

Ensures more stable and reliable signal connection, superior vibration resistance, and convenience for mass production

▶ Shield Design

Resistant to signal interference and dust, while supporting customized LOGO to enhance customer brand value

▶ Compact Design

Features a small size and flexible design, making it suitable for various sizes of products, especially those with limited structural space

Excellent Quality

▶ Rigorous Testing

The SOMs undergo six rigorous tests, including signal tests, high and low temperature tests, aging tests, electrostatic tests, over 5,000 power-on and power-off tests, and MTBF tests, to ensure product stability.

▶ Compliance with International Certification Standards

Adopting international SGS as a certification testing partner, we provide CE and RoHS certification reports

▶ Smart Factory

MYIR's own factory, equipped with advanced production equipment and adopting MES systems, ensures high-quality and traceability of products

Competitive cost

▶ Scale Effect

With over one million SOMs sold annually, we achieve excellent bulk material costs through mass production

▶ Packaging Advantage

The SOMs adopt an LCC/LGA packaging design, which saves the cost of board-to-board connectors

▶ Supply Chain Management

Establishing close cooperation relationships with original manufacturers enables us to obtain more competitive chip price support

Advantages of MYIR's System-On-Modules



Quick Delivery and Long Lifecycle

▶ Short lead time

By implementing a comprehensive inventory management system for our standard products, we guarantee a shortened lead time for both sample and bulk orders.

▶ Long lifecycle

We guarantee a supply duration exceeding 10 years. In case of material discontinuation, we have established a comprehensive product change process and notification policy to mitigate any potential disruptions.

▶ Long-term maintenance

Our commitment extends to providing ongoing software maintenance and regular updates for the BSP package, ensuring its continued reliability and performance over time.

Full-service technical support

▶ Pre-sales service

We offer optimal platform recommendations, feasibility assessments, software and hardware framework setups, and prototype function verifications during the selection phase, guiding you through the initial stages of your project seamlessly.

▶ In-sales service

During the design phase, we provide schematic diagram and PCB guidance and review, driver debugging, middleware transplantation, and system optimization, ensuring the smooth progress of your development efforts.

▶ After-sales service

We maintain prompt email communication with our FAE team, offering remote assistance to resolve any issues that may arise. We document the entire process and provide an 8D report, ensuring transparency and continuous improvement.

Abundant development resources

▶ Hardware documentation

Comprehensive product manuals, hardware design guides, hardware user manuals, and pin usage tables for our SOMs, facilitating easy integration and customization.

▶ Software documentation

Detailed quick start guides, software development guides, software evaluation guides, and application notes, enabling efficient software development and deployment.

▶ Design materials

Access to our baseboard schematic and PCB source files, BSP software source code, and industry application demos, providing a solid foundation for your design and development efforts.

ST | MYC-YF13X

- ST STM32MP135 Processor, Cortex-A7@1.0GHz
- DDR3L, Nand Flash/eMMC, EEPROM
- LCD-TFT Parallel Display Interface, 16-bit Camera, 2x USB2.0, 2x CAN-FD, 2x Gigabit Ethernet
- 37mm x 39mm; LCC Package, 148-pin; -40°C~+85°C Industrial; Linux OS



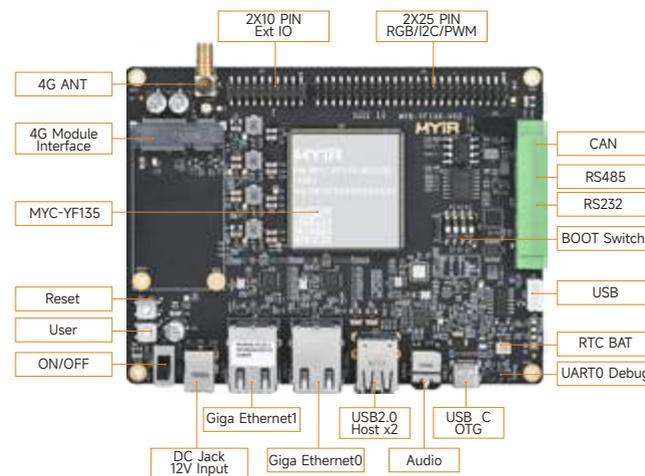
● **Part Selections** (Other Configurations can be Customized for Mass Production)

SOM Part Number	CPU	CPU Cores and Clock Speed (Max)	RAM	ROM	Others	Package	Working Temp.	Dimensions	Software	Development Board Part Number
MYC-YF135-256N256D-100-I	STM32MP135DAF7	Cortex-A7@1.0GHz	256MB DDR3	256MB Nand Flash	32kbit EEPROM	LCC 148PIN	-40°C~+85°C	37mm x 39mm	Linux	MYD-YF135-256N256D-100-I
MYC-YF135-4E512D-100-I			512MB DDR3	4GB eMMC						MYD-YF135-4E512D-100-I

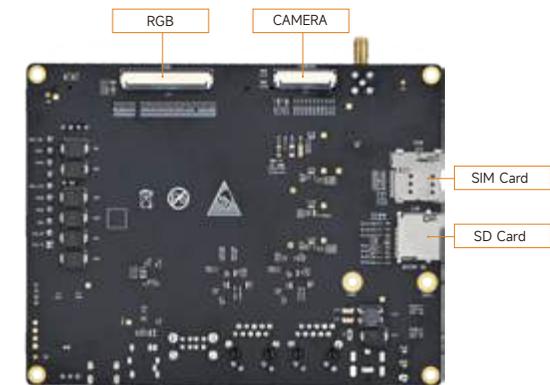
● **Peripherals/Interfaces**

Communications	2×RGMII, 2×CAN FD, 2×USB2.0, 8×UART, 5×SPI, 5×I2C
Multimedia	RGB, DCMI, 2×SAI, 3×I2S
Others	12-bit 19-ch ADC, 12-bit 18-ch ADC, SWD

● **Key Applications**



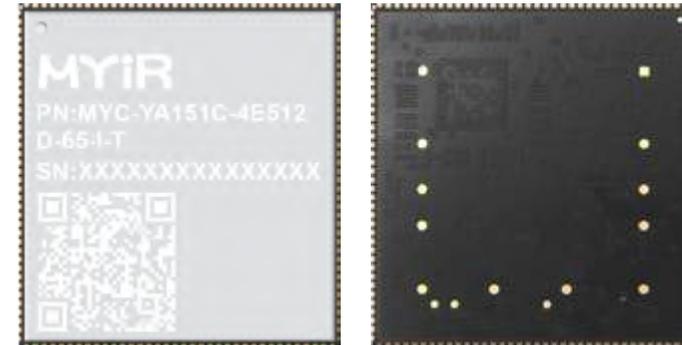
MYD-YF13X Development Board Top-view



MYD-YF13X Development Board Bottom-view

ST | MYC-YA15XC-T

- ST STM32MP151 Processor, Cortex-A7@650MHz + Cortex-M4@209MHz
- DDR3L, Nand Flash/eMMC, EEPROM
- Gigabit Ethernet, 2x USB 2.0, 8x UART, 6x SPI, 6x I2C
- 37mm x 39mm; LCC Package, 148-pin; 0 to 70 °C Commercial, -40°C~+85°C Industrial; Linux OS

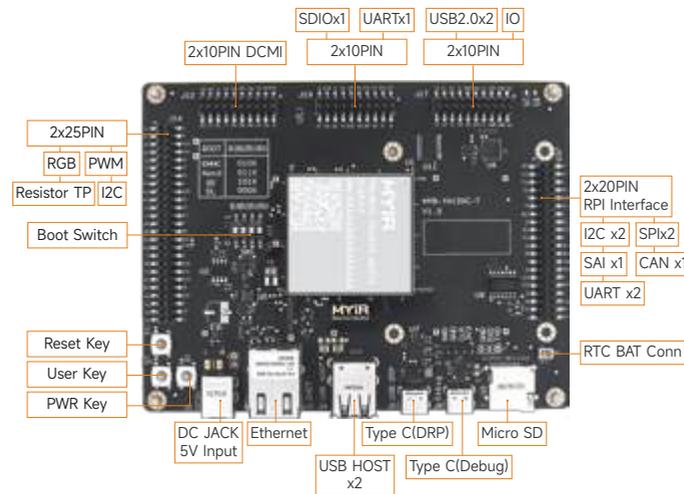


● **Part Selections** (Other Configurations can be Customized for Mass Production)

SOM Part Number	CPU	CPU Cores and Clock Speed (Max)	RAM	ROM	Others	Package	Working Temp.	Dimensions	Software	Development Board Part Number
MYC-YA151C-256N256D-65-C-T	STM32MP151AAC3	Cortex-A7@650MHz +Cortex-M4@209MHz	256MB DDR3	256MB Nand Flash	32Kbit EEPROM	LCC 148PIN	0°C~+70°C	37mm × 39mm	Linux	MYD-YA151C-V2-256N256D-65-C-T
-40°C~+85°C							MYD-YA151C-V2-256N256D-65-I-T			
0°C~+70°C			512MB DDR3	4GB eMMC			MYD-YA151C-4E512D-65-C-T			
-40°C~+85°C							MYD-YA151C-4E512D-65-I-T			

● **Peripherals/Interfaces**

Communications	RGMI, 2×USB2.0, 8×UART, 6×SPI, 6×I2C
Multimedia	RGB, DCMI, 4×SAI, 3×I2S
Others	2x16-bit 20-ch ADC, SWD



MYD-YA15XC-T Development Board Top-view



MYD-YA15XC-T Development Board Bottom-view

● **Key Applications**



HMI



Medical Device



Industrial Manufacturing



Petroleum & Chemical

ST | MYC-YA157C-V3

- ST STM32MP157 Processor, 2x Cortex-A7@650MHz + Cortex-M4@209MHz
- DDR3, eMMC, Ethernet PHY
- Gigabit Ethernet, 2x CAN, 2x USB2.0, 8x UART, 6x SPI, 6x I2C
- 43mm x 45mm; LCC Package, 164-pin; 0 to 70 °C Commercial, -40°C~+85°C Industrial; Linux / Ubuntu OS



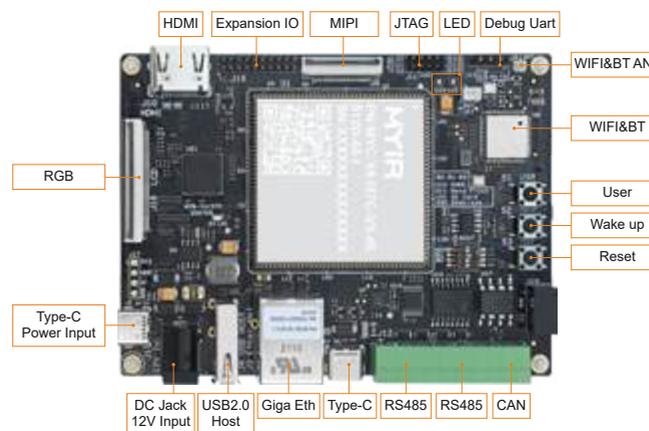
● **Part Selections** (Other Configurations can be Customized for Mass Production)

SOM Part Number	CPU	CPU Cores and Clock Speed (Max)	RAM	ROM	Others	Package	Working Temp.	Dimensions	Software	Development Board Part Number
MYC-YA157C-V3-4E512D-65-C	STM32MP157AAC3	2xCortex-A7@650MHz +Cortex-M4@209MHz	512MB DDR3L	4GB eMMC	Ethernet PHY	LCC 164PIN	0°C~+70°C	43mm x 45mm	Linux Ubuntu	MYD-YA157C-V3-4E512D-65-C
MYC-YA157C-V3-4E512D-65-I							-40°C~+85°C			MYD-YA157C-V3-4E512D-65-I

● **Peripherals/Interfaces**

Communications	RGMII, 2×CAN FD, 2×USB2.0, 8×UART, 6×SPI, 6×I2C
Multimedia	RGB, MIPI DSI, 4×SAI, 3×I2S
Others	2×16-bit 20-ch ADC, SWD

● **Key Applications**



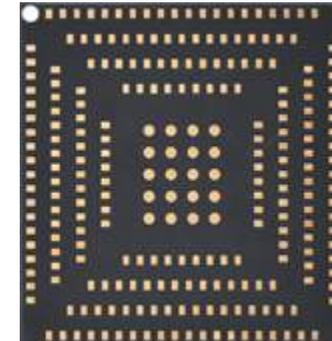
MYD-YA157C-V3 Development Board Top-view



MYD-YA157C-V3 Development Board Bottom-view

ST | MYC-LD25X

- ST STM32MP257D, 2x Cortex-A35@1.5GHz + Cortex-M33@400MHz
- LPDDR4, eMMC, EEPROM
- Neural Processing Unit (NPU) operating at up to 1.35 TOPS, 3D GPU
- 3x Gigabit Ethernet, 3x CAN FD, USB3.0, 5x UART, 8x SPI, 7x I2C
- 39mm x 37mm; LGA Package, 252-pin; -40°C~+85°C Industrial; Linux / Debian



● **Part Selections** (Other Configurations can be Customized for Mass Production)

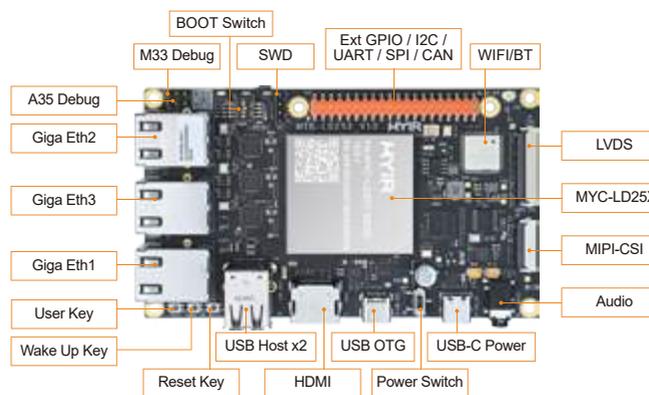
SOM Part Number	CPU	CPU Cores and Clock Speed (Max)	RAM	ROM	Others	Package	Working Temp.	Dimensions	Software	Development Board Part Number
MYC-LD257-8E1D-150-I	STM32MP257DAK3	2xCortex-A35@1.5GHz+ Cortex-M33@400MHz	1GB LPDDR4	8GB eMMC	256Kbit EEPROM	LGA 252PIN	-40°C~+85°C	39mm × 37mm	Linux Debian	MYD-LD257-8E1D-150-I
MYC-LD257-8E2D-150-I			2GB LPDDR4							MYD-LD257-8E2D-150-I

● **Peripherals/Interfaces**

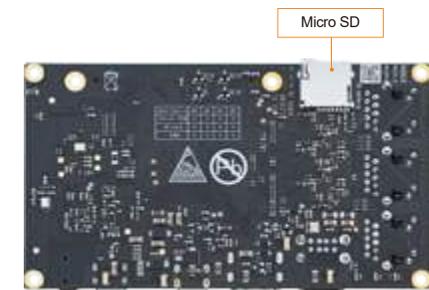
Communications	3xRGMII, USB2.0 HOST, USB3.0 OTG/PCIE2.0, 4xUSART, 5xUART, 8xSPI, 7xI2C, 4xI3C, 3xCAN FD, 2xSD/MCC
Multimedia	Parallel RGB, MIPI DSI, LVDS, MIPI CSI , DCMI, 4xSAI
Others	JTAG, SWD

● **Key Applications**

- Industrial HMI
- Edge Computing Gateway
- New Energy Charging Pile
- Energy Storage EMS Systems



MYD-LD25X Development Board Top-view



MYD-LD25X Development Board Bottom-view

NXP | MYC-Y6ULX-V2

- NXP i.MX 6UL/i.MX 6ULL Processor, Cortex-A7@528MHz
- DDR3, Nand FLASH/eMMC, On-board Gigabit Ethernet PHY
- 2x USB2.0, 2x 10/100Mbps Ethernet, 2x CAN, 8x UART, 4x SPI, 4x I2C
- 37mm x 39mm; LCC Package, 140-pin; 0°C~+70°C Commercial; -40°C~+85°C Industrial;
- Linux OS



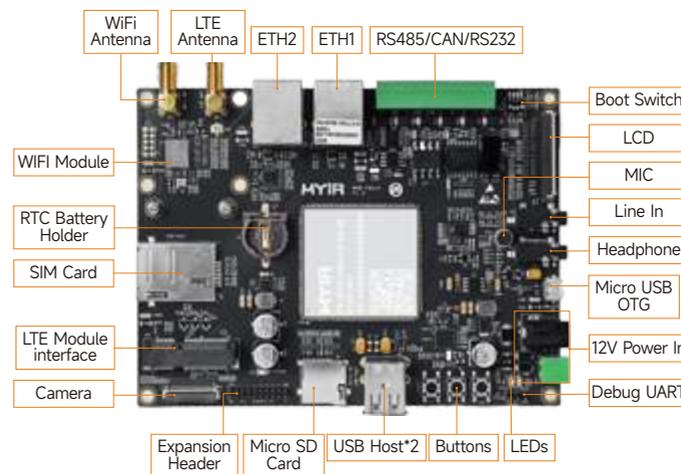
● **Part Selections** (Other Configurations can be Customized for Mass Production)

SOM Part Number	CPU	CPU CPU Cores and Clock Speed (Max)	RAM	ROM	Others	Package	Working Temp.	Dimensions	Software	Development Board Part Number
MYC-Y6ULY2-V2-256N256D-50-C	MCIMX6Y2CVM05AB	Cortex-A7@528MHz	256MB DDR3	256MB Nand FLASH	Ethernet PHY	LCC 140PIN	0°C~+70°C	37mm x 39mm	Linux	MYD-Y6ULY2-V2-256N256D-50-C
MYC-Y6ULY2-V2-256N256D-50-I							-40°C~+85°C			MYD-Y6ULY2-V2-256N256D-50-I
MYC-Y6ULY2-V2-4E512D-50-C			0°C~+70°C	MYD-Y6ULY2-V2-4E512D-50-C						
MYC-Y6ULY2-V2-4E512D-50-I			-40°C~+85°C	MYD-Y6ULY2-V2-4E512D-50-I						
MYC-Y6ULG2-V2-256N256D-50-I	MCIMX6G2CVM05AB		256MB DDR3	256MB Nand FLASH						MYD-Y6ULG2-V2-256N256D-50-I

● **Peripherals/Interfaces**

Communications	2×RMII, 2×CAN, 2×USB2.0, 8×UART, 4×SPI, 4×I2C
Multimedia	RGB, Parallel CSI , 3×I2S
Others	2×12bit 10ch ADC, JTAG

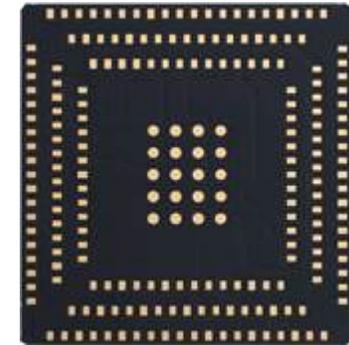
● **Key Applications**



MYD-Y6ULX-V2 Development Board Top-view

NXP | MYC-LMX91

- NXP i.MX 91 Processor, Cortex-A55@1.4GHz
- 1GB LPDDR4, 8GB eMMC, 32KB EEPROM
- 2x Gigabit Ethernet, 2x USB, 8x UART, 8x SPI, 2x CAN-FD, RGB Display
- 37mm x 39mm, LGA Package, 218PIN, -40 ~ +85°C Industrial
- Linux OS



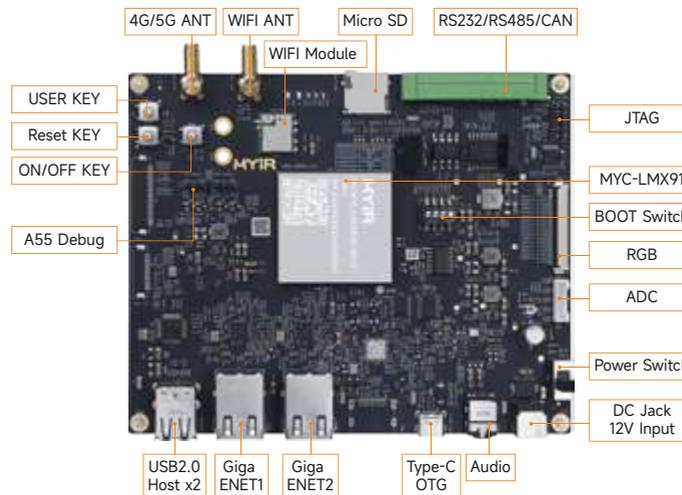
• **Part Selections** (Other Configurations can be Customized for Mass Production)

SOM Part Number	CPU	CPU Cores and Clock Speed (Max)	RAM	ROM	Others	Package	Working Temp.	Dimensions	Software	Development Board Part Number
MYC-LMX9131-8E1D-140-I	MIMX9131CVVXJAA	Cortex-A55@1.4GHz	1GB LPDDR4	8GB eMMC	32KB EEPROM	LGA 218PIN	-40°C~+85°C	37mm x 39mm	Linux	MYD-LMX9131-8E1D-140-I

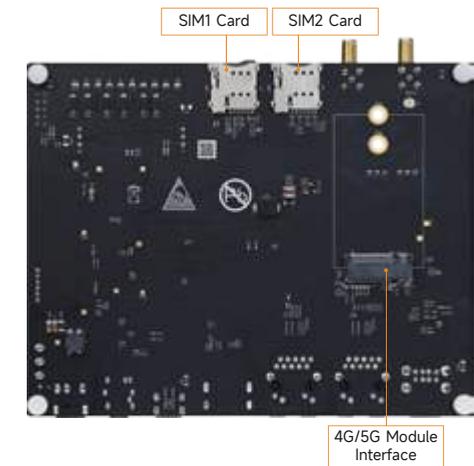
• **Peripherals/Interfaces**

Communications	2xRMII, 2xCAN FD, 2xUSB2.0, 8xUART, 8xSPI, 8xI2C, 2xI3C, 2xuSDHC
Multimedia	RGB, Parallel CSI, 3xSAI
Others	4xADC, JTAG, SWD

• **Key Applications**



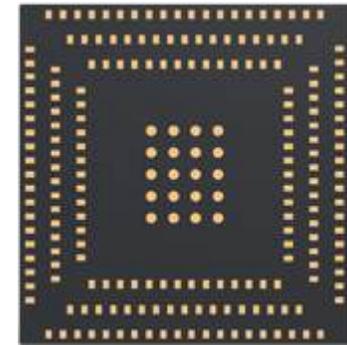
MYD-LMX91 Development Board Top-view



MYD-LMX91 Development Board Bottom-view

NXP | MYC-LMX9X

- NXP i.MX 93 Processor, 2*Cortex-A55@1.7GHz + Cortex-M33@250MHz
- 0.5 TOPS NPU for Cost-effective and Energy-efficient ML Applications
- 2x Gigabit Ethernet (one TSN-based), 2x CAN FD, 8x UART, 8x I2C, 8x SPI
- LPDDR4, eMMC, EEPROM, 37mm x 39mm; LGA Package, 218-pin; -40°C~+85°C Industrial
- Linux OS (Yocto based with QT / Debian)



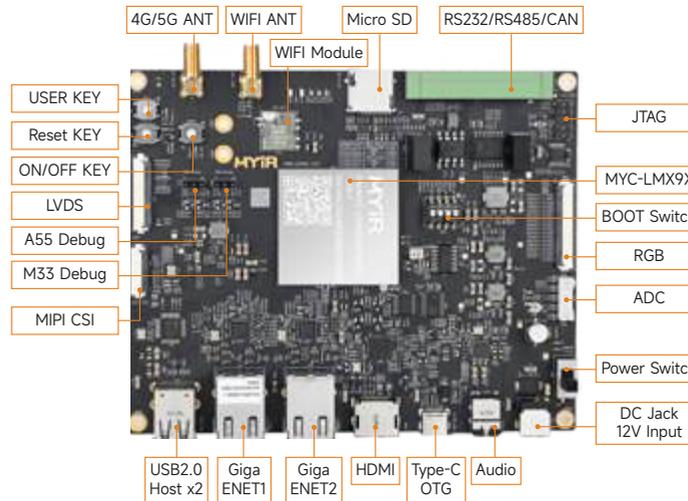
● **Part Selections** (Other Configurations can be Customized for Mass Production)

SOM Part Number	CPU	CPU Cores and Clock Speed (Max)	RAM	ROM	Others	Package	Working Temp.	Dimensions	Software	Development Board Part Number
MYC-LMX9352-8E1D-170-I	MIMX9352CVVXMAB	2xCortex-A55@1.7GHz+ Cortex-M33@250MHz	1GB LPDDR4	8GB eMMC	32KB EEPROM	LGA 218PIN	-40°C~+85°C	37mm x 39mm	Linux Debian	MYD-LMX9352-8E1D-170-I
MYC-LMX9352-8E2D-170-I			2GB LPDDR4							MYD-LMX9352-8E2D-170-I

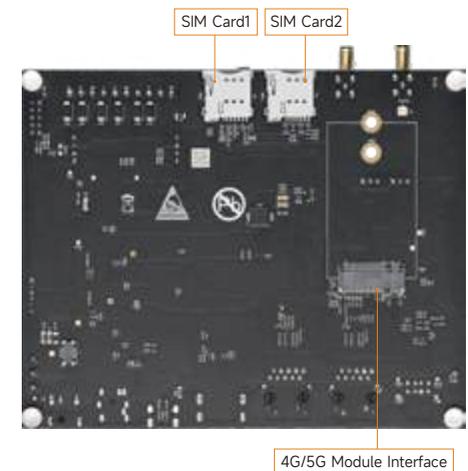
● **Peripherals/Interfaces**

Communications	2xRGMII, 2xCAN FD, 2xUSB2.0, 8xUART, 8xSPI, 8xI2C, 2xI3C
Multimedia	MIPI DSI, LVDS, RGB, MIPI CSI, Parallel CSI , 3xSAI
Others	12bit 4ch ADC, JTAG

● **Key Applications**



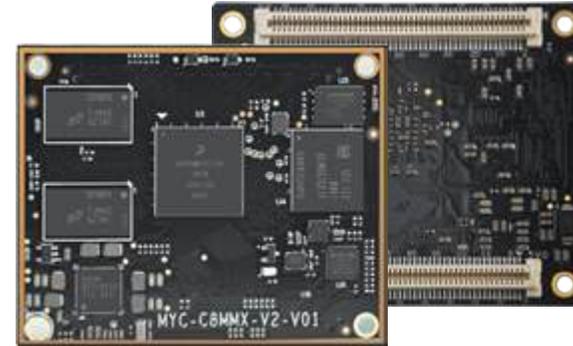
MYD-LMX9X Development Board Top-view



MYD-LMX9X Development Board Bottom-view

NXP | MYC-C8MMX-V2

- NXP i.MX 8M Mini Processor, 4*Cortex-A53@1.8GHz + Cortex-M7@400MHz
- DDR4, eMMC, QSPI Flash, On-board Gigabit Ethernet PHY
- 2x USB2.0, Gigabit Ethernet, PCIE2.0, 4x UART, 3x SPI, 3x I2C
- 49mm x 60mm; 200-pin Board-to-Board Connectors; 0°C~+70°C Commercial; -40°C~+85°C Industrial
- Linux / Android OS



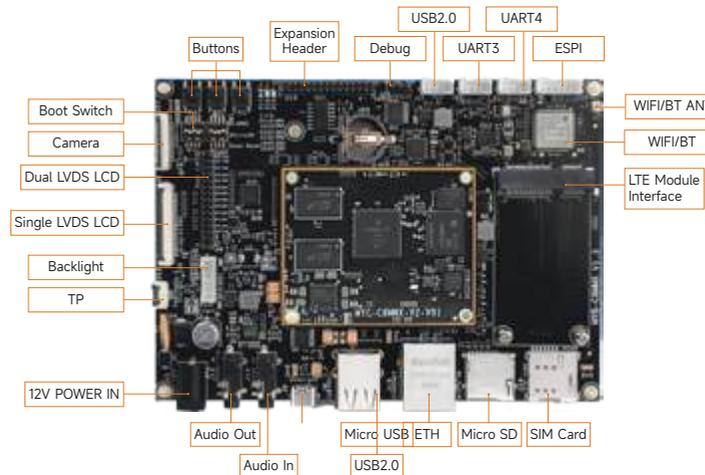
• **Part Selections** (Other Configurations can be Customized for Mass Production)

SOM Part Number	CPU	CPU Cores and Clock Speed (Max)	RAM	ROM	Others	Package	Working Temp.	Dimensions	Software	Development Board Part Number
MYC-C8MMQ6-V2-8E2D-180-C	MIMX8MM6DVTLZAA	4xCortex-A53@1.8GHz +Cortex-M4@400MHz	2GB DDR4	8GB eMMC	Ethernet PHY 32MB QSPI FLASH	B2B 200PIN	0°C~+70°C	49mm × 60mm	Linux Android	MYD-C8MMQ6-V2-8E2D-180-C
MYC-C8MMQ6-V2-8E2D-160-I	MIMX8MM6CVTKZAA	4xCortex-A53@1.6GHz +Cortex-M4@400MHz					-40°C~+85°C			MYD-C8MMQ6-V2-8E2D-160-I

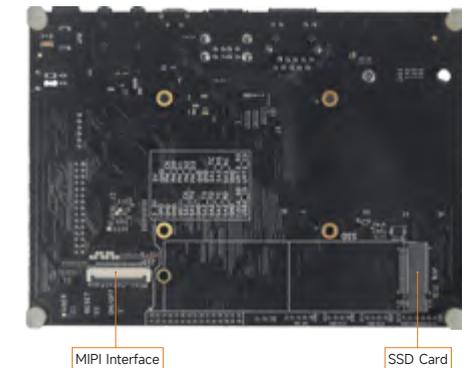
• **Peripherals/Interfaces**

Communications	RGMI, PCIE2.0, 2xUSB2.0, 4xUART, 3xSPI, 3xI2C
Multimedia	MIPI DSI, MIPI CSI, 5xSAI
Others	JTAG

• **Key Applications**



MYD-C8MMX-V2 Development Board Top-view



MYD-C8MMX-V2 Development Board Bottom-view

NXP | MYC-JX8MPQ

- NXP i.MX 8M Plus Processor, 4*Cortex-A53@1.6GHz + Cortex-M7@800MHz
- 2.3 TOPS NPU for Extensive AI/ML Capabilities; 800MHz Audio DSP, Dual Camera Interfaces (ISP), 3D GPU
- LPDDR4, eMMC, QSPI Flash; 2x USB3.0, 2x Gigabit Ethernet, 2x CAN FD, 4x UART, 3x SPI, 6x I2C
- 45mm x 82mm; MXM Package, 314-pin; -40°C~+85°C Industrial; Linux OS



● **Part Selections** (Other Configurations can be Customized for Mass Production)

SOM Part Number	CPU	CPU Cores and Clock Speed (Max)	RAM	ROM	Others	Package	Working Temp.	Dimensions	Software	Development Board Part Number
MYC-JX8MPQ-8E2D-160-I	MIMX8ML8CVNKZAB	4xCortex-A53@1.6GHz +Cortex-M7@800MHz	2GB LPDDR4	8GB eMMC	32MB QSPI FLASH	MXM 314PIN	-40°C~+85°C	45mm x 82mm	Linux	MYD-JX8MPQ-8E2D-160-I
MYC-JX8MPQ-8E4D-160-I			4GB LPDDR4							MYD-JX8MPQ-8E4D-160-I

● **Peripherals/Interfaces**

Communications	2xRGMII, PCIE3.0, 2xUSB3.0, 2xCAN FD, 4xUART, 3xSPI, 6xI2C
Multimedia	HDMI, MIPI-DSI, LVDS, 2xMIPI CSI, 6xSAI
Others	JTAG

● **Key Applications**



HMI



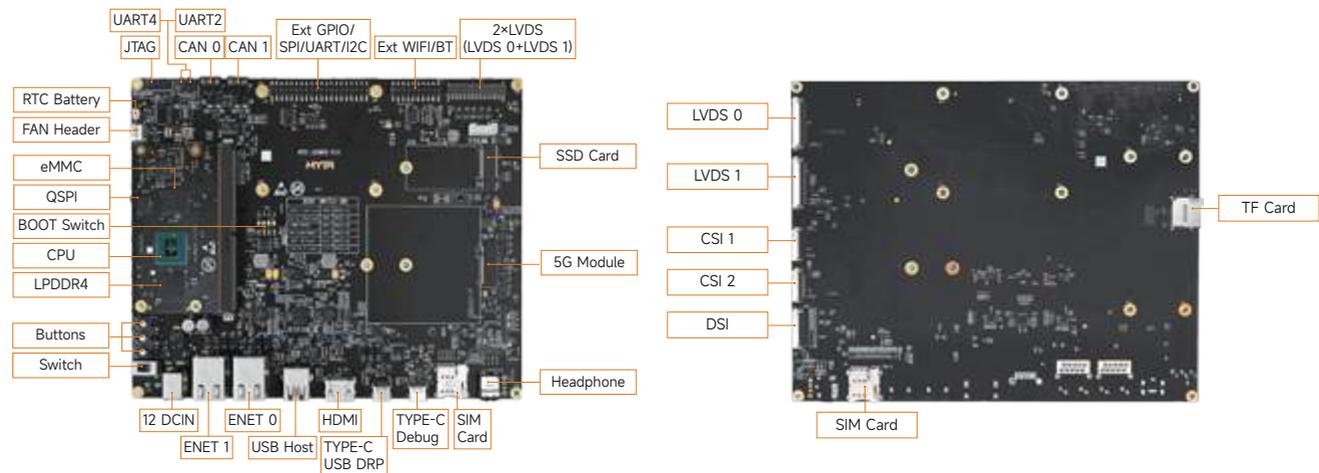
High-performance AI Devices



Industrial Computers



Edge Computing



MYD-JX8MPQ Development Board Top-view

MYD-JX8MPQ Development Board Bottom-view

NXP | MYC-J1028X

- NXP LS1028A Processor, 2*Cortex-A72@1.5GHz, DDR4, eMMC, EEPROM
- 6x Gigabit Ethernet (TSN-based), 2x USB3.0, 2x CAN FD, 6x UART, 3x SPI, 1x SATA3.0
- Support DP Display (DP1.3 and eDP 1.4, resolution up to 4K@60FPS)
- 45mm x 82mm; MXM 3.0 Gold-finger Interface, 314-pin; -40°C~+85°C Industrial;
- Supports Ubuntu and Real-time Edge Images based on Linux



● **Part Selections** (Other Configurations can be Customized for Mass Production)

SOM Part Number	CPU	CPU Cores and Clock Speed (Max)	RAM	ROM	Others	Package	Working Temp.	Dimensions	Software	Development Board Part Number
MYC-J1028N-8E2D-150-1	LS1028AXN7PQA	2xCortex-A72@1.5GHz	2GB DDR4	8GB eMMC	32Kbit EEPROM	MXM 314PIN	-40°C~+85°C	45mm x 82mm	Linux Ubuntu	MYD-J1028N-8E2D-150-1

● **Peripherals/Interfaces**

Communications	SGMII, QSGMII, RGMII, 2xPCIe3.0, SATA 3.0, 2xUSB3.0, 2xCAN FD, 6xUART, 3xSPI, 8xI2C
Multimedia	eDP, 6xSAI
Others	JTAG

● **Key Applications**



Automotive Electronics



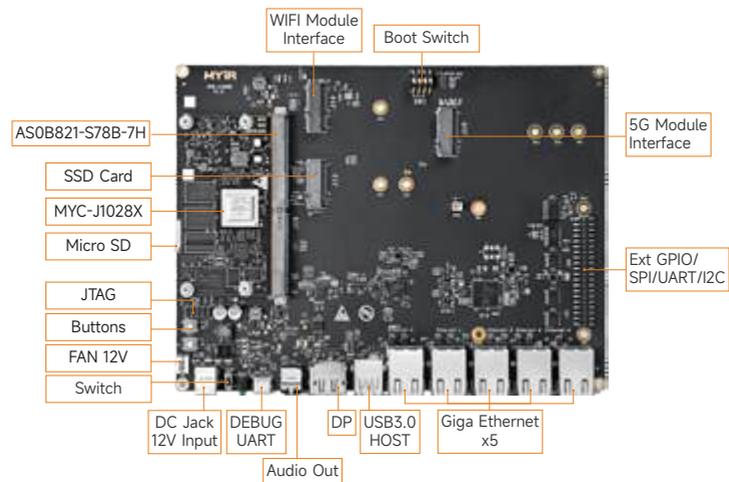
Industrial Routers



Industrial Control



Edge Computing



MYD-J1028X Development Board Top-view



MYD-J1028X Development Board Bottom-view

NXP & AMD | MYC-JX8MMA7

- i.MX 8M Mini + XC7A25T Aritx-7, 4*Cortex-A53@1.8GHz + Cortex-M4@400MHz + FPGA
- ARM: LPDDR4, eMMC, QSPI Flash; FPGA: DDR3, QSPI Flash
- Integrated 2D/3D GPU and 1080p VPU, Two PMIC (one for ARM and one for FPGA)
- 45mm x 82mm; MXM 3.0 Gold-finger Interface, 314-pin; -40°C~+85°C Industrial; Linux OS



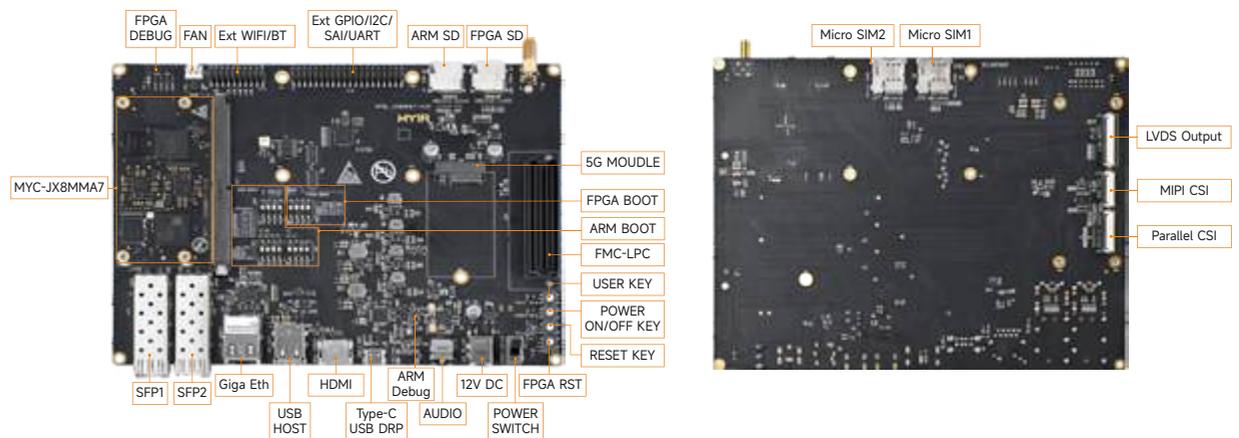
● **Part Selections** (Other Configurations can be Customized for Mass Production)

SOM Part Number	CPU	CPU Cores and Clock Speed (Max)	RAM	ROM	Others	Package	Working Temp.	Dimensions	Software	Development Board Part Number
MYC-JX8MMA7-8E2D-32Q256D-160-I	ARM: MIMX8MM6CVTKZAA FPGA: XC7A25T-2CSG325I	4*Cortex-A53@1.6GHz+ Cortex-M4@400MHz FPGA: 23K	ARM: 2GB LPDDR4	ARM: 8GB eMMC	32MB QSPI FLASH	MXM 314PIN	-40°C~+85°C	45mm x 82mm	Linux	MYD-JX8MMA7-8E2D-32Q256D-160-I
MYC-JX8MMA7-8E2D-32Q256D-180-C	ARM: MIMX8MM6DVTLZAA FPGA: XC7A25T-2CSG325C	4*Cortex-A53@1.8GHz+ Cortex-M4@400MHz FPGA: 23K	FPGA: 256MB DDR3	FPGA: 32MB QSPI FLASH			0°C~+70°C			MYD-JX8MMA7-8E2D-32Q256D-180-C

● **Peripherals/Interfaces**

Communications	RGMI, 2*USB2.0, 4*UART, 2*SPI, 2*I2C, 3*GTP
Multimedia	MIPI DSI, MIPI CSI, 3*SAI
Others	JTAG

● **Key Applications**



MYD-JX8MMA7 Development Board Top-view

MYD-JX8MMA7 Development Board Bottom-view

AMD XILINX | MYC-J7A100T

- AMD/Xilinx XC7A100T Artix-7 FPGA (XC7A100T-2FGG484I)
- DDR3, QSPI FLASH, EEPROM
- Supports Development by Xilinx's Vivado Design Suite
- 69.6mm x 40mm; MXM Package, 260-pin; -40°C~+85°C Industrial



• **Part Selections** (Other Configurations can be Customized for Mass Production)

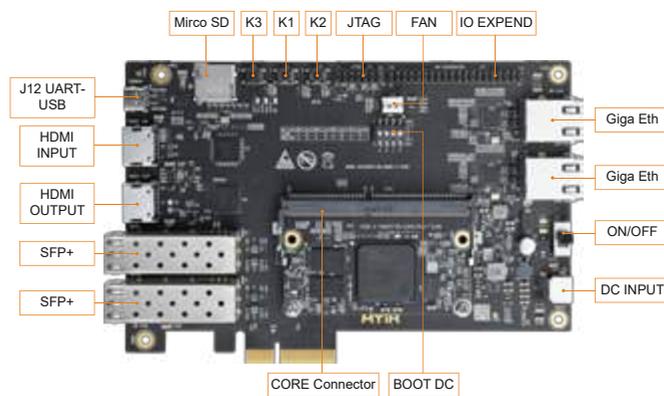
SOM Part Number	CPU	CPU Cores and Clock Speed (Max)	RAM	ROM	Others	Package	Working Temp.	Dimensions	Software	Development Board Part Number
MYC-J7A100T-32Q512D-I	XC7A100T-2FGG484I	-	512MB DDR3	32MB QSPI FLASH	32KB EEPROM	MXM 260PIN	-40°C~+85°C	69.6mm x 40mm	Xilinx's Vivado Design Suite	MYD-J7A100T-32Q512D-I

• **Signals Routed to Pins**

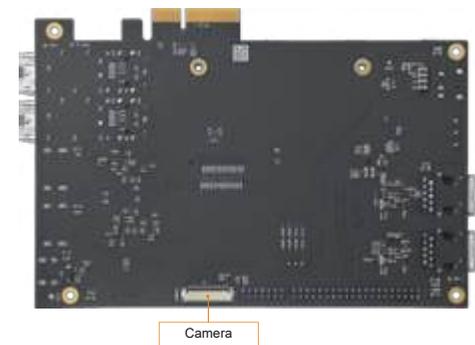
0.5mm pitch MXM Gold-finger-edge-card Expansion Interface

Item	Number of I/Os	Description
Bank13	35	There are 178 I/Os in total, which are defined according to different requirements. Signal lines with the same function are located on the same bank.
Bank14	45	
Bank15	48	
Bank16	50	
MGTP	20	High-Speed Serial Interfaces
JTAG	4	JTAG Debug

• **Key Applications**



MYD-J7A100T Development Board Top-view



MYD-J7A100T Development Board Bottom-view

AMD XILINX | MYC-C7Z010/20-V2

- Xilinx XC7Z010/20 Processor, 2x Cortex-A9@667/766MHz+Artix 7 FPGA
- DDR3, eMMC, QSPI Flash
- On-board Gigabit Ethernet PHY
- 75mm x 55mm; B2B Package, 2x140-pin; -40°C~+85°C Industrial; Linux OS



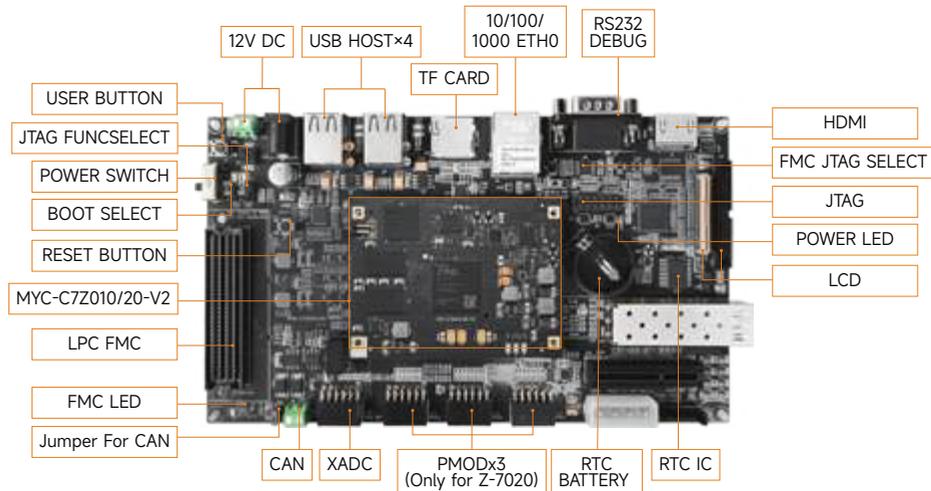
● **Part Selections** (Other Configurations can be Customized for Mass Production)

SOM Part Number	CPU	CPU Cores and Clock Speed (Max)	RAM	ROM	Others	Package	Working Temp.	Dimensions	Software	Development Board Part Number
MYC-C7Z010-V2-4E1D-667-I	xc7z010-1clg400	2×Cortex-A9@667Hz +Atrix 7 FPGA (28K)	1GB DDR3	4GB eMMC	32MB QSPI Flash Ethernet PHY USB PHY	B2B 2×140PIN	-40°C~+85°C	75mm × 55mm	Linux	MYD-C7Z010-V2-4E1D-667-I
MYC-C7Z020-V2-4E1D-766-I	xc7z020-2clg400	2×Cortex-A9@766Hz +Atrix 7 FPGA (85K)								MYD-C7Z020-V2-4E1D-766-I
MYC-C7Z010-V2-4E1D-667-C	xc7z010-1clg400	2×Cortex-A9@667Hz +Atrix 7 FPGA (28K)					MYD-C7Z010-V2-4E1D-667-C			
MYC-C7Z020-V2-4E1D-766-C	xc7z020-2clg400	2×Cortex-A9@766Hz +Atrix 7 FPGA (85K)					MYD-C7Z020-V2-4E1D-766-C			

● **Peripherals/Interfaces**

Communications	RGMI, USB2.0, CAN, 2×SPI, 2x I2C, XADC
FPGA Expansion IO	141PIN (FPGA_XC7020) , 114PIN (FPGA_XC7010)

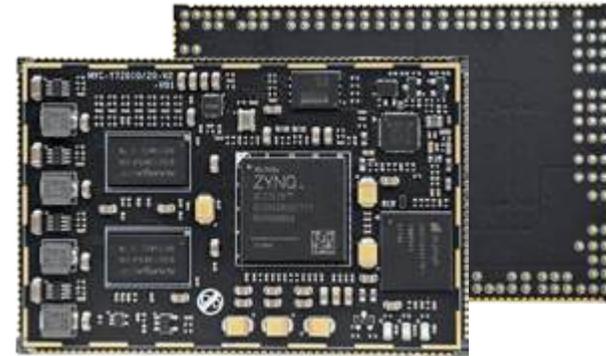
● **Key Applications**



MYD-C7Z010/20-V2 Development Board Top-view

AMD XILINX | MYC-Y7Z010/20-V2

- Xilinx XC7Z010/20 Processor, 2x Cortex-A9@667/766MHz+Artix 7 FPGA
- DDR3, eMMC, QSPI Flash
- On-board Gigabit Ethernet PHY
- 75mm x 50mm; LCC Package, 180-pin; -40°C~+85°C Industrial; Linux OS



● **Part Selections** (Other Configurations can be Customized for Mass Production)

SOM Part Number	CPU	CPU Cores and Clock Speed (Max)	RAM	ROM	Others	Package	Working Temp.	Dimensions	Software	Development Board Part Number
MYC-Y7Z010-V2-4E512D-667-I	xc7z010-1clg400	2*Cortex-A9@667Hz +Atrix 7 FPGA (28K)	512MB DDR3	4GB eMMC	16MB QSPI Flash Ethernet PHY	LCC 180PIN	-40°C~+85°C	75mm × 50mm	Linux	MYD-Y7Z010-V2-4E1D-667-I
MYC-Y7Z020-V2-4E512D-766-I	xc7z020-2clg400	2*Cortex-A9@766Hz +Atrix 7 FPGA (85K)								MYD-Y7Z020-V2-4E1D-766-I

● **Peripherals/Interfaces**

Communications	RGMI, USB2.0, CAN, 2×SPI, 2× I2C, JTAG
FPGA Expansion IO	Expandable 121PIN

● **Key Applications**



Automotive



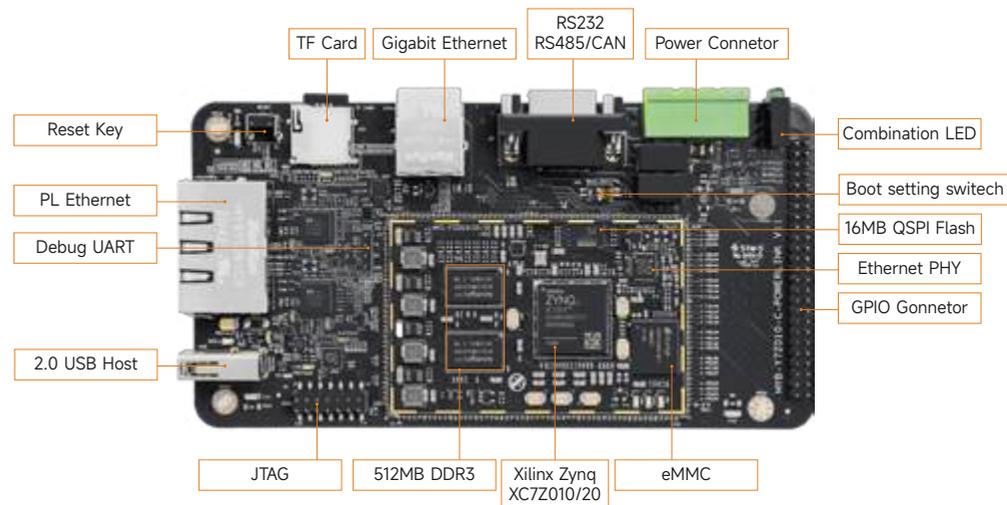
Medical Device



Industrial Control



Artificial Intelligence (AI)



MYD-Y7Z010/20-V2 Development Board Top-view

AMD XILINX | MYC-C7Z015

- Xilinx XC7Z015 Processor, 2x Cortex-A9@766MHz+Artix 7 FPGA
- DDR3, eMMC, QSPI Flash
- On-board Gigabit Ethernet PHY
- 75mm x 55mm; B2B Package, 2x140-pin; -40°C~+85°C Industrial; Linux OS



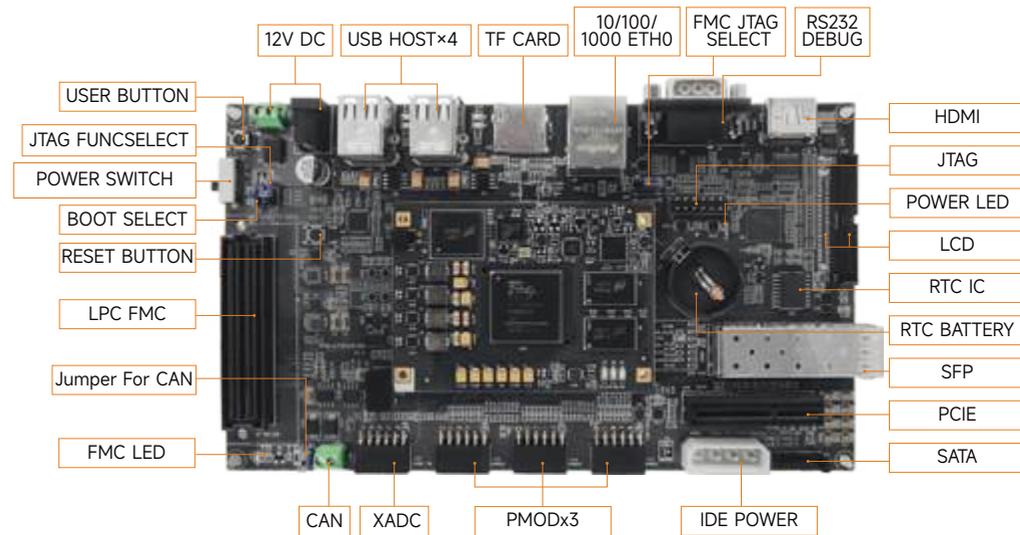
● **Part Selections** (Other Configurations can be Customized for Mass Production)

SOM Part Number	CPU	CPU Cores and Clock Speed (Max)	RAM	ROM	Others	Package	Working Temp.	Dimensions	Software	Development Board Part Number
MYC-C7Z015-4E1D-766-I	xc7z015-2clg485	2xCortex-A9@766Hz +Artix 7 FPGA (74K)	1GB DDR3	4GB eMMC	32MB QSPI Flash Ethernet PHY USB PHY	B2B 2x140PIN	-40°C~+85°C	75mm × 55mm	Linux	MYD-C7Z015-4E1D-766-I

● **Peripherals/Interfaces**

Communications	RGMII, USB2.0, CAN, 2xSPI, 2xI2C, 2xXADC, SFP, PCIE, SATA
FPGA Expansion IO	137PIN (FPGA_XC7015)

● **Key Applications**



MYD-C7Z015 Development Board Top-view



MYC-CZU3EG/4EV/5EV-V2

- Zynq UltraScale+ ZU3EG /ZU4EV /ZU5EV MPSoC, 4x Cortex-A53@1.2GHz+2x Cortex-R5@600MHz
- DDR4, eMMC, QSPI Flash
- USB 3.0, Gigabit Ethernet, CAN, TF, DP, PCIe, SATA, HDMI, LCD
- 60mm x 52mm; B2B Package, 2x160-pin; 0°C~+70°C Commercial; Linux OS



● **Part Selections** (Other Configurations can be Customized for Mass Production)

SOM Part Number	CPU	CPU Cores and Clock Speed (Max)	RAM	ROM	Others	Package	Working Temp.	Dimensions	Software	Development Board Part Number
MYC-CZU3EG-V2-4E4D-1200-C	XCZU3EG-1SFVC784	ARM: 4xA53@1200MHz+2xR5@533MHz + UltraScale+ FPGA 154K	4GB DDR4	4GB eMMC	128MB QSPI Flash Ethernet PHY USB PHY	B2B 2x160PIN	0°C~+70°C	60mm × 52mm	Linux	MYD-CZU3EG-V2-4E4D-1200-C
MYC-CZU4EV-V2-4E4D-1200-I-FAN	XCZU4EV-2SFVC784	ARM: 4xA53@1200MHz+2xR5@533MHz + UltraScale+ FPGA 192K					-40°C~+85°C			MYD-CZU4EV-V2-4E4D-1200-C
MYC-CZU5EV-V2-4E4D-1200-I-FAN	XCZU5EV-2SFVC784	ARM: 4xA53@1200MHz+2xR5@533MHz + UltraScale+ FPGA 256K					MYD-CZU5EV-V2-4E4D-1200-C			

● **Peripherals/Interfaces**

Communications	RGMII, CAN, USB3.0, USB_UART, 2xPMOD, PCIE2.0, DP, SATA3.0, 4xSFP (Only for 4EV/5EV)
FPGA Expansion IO	156PIN (FPGA)

● **Key Applications**



Data Center



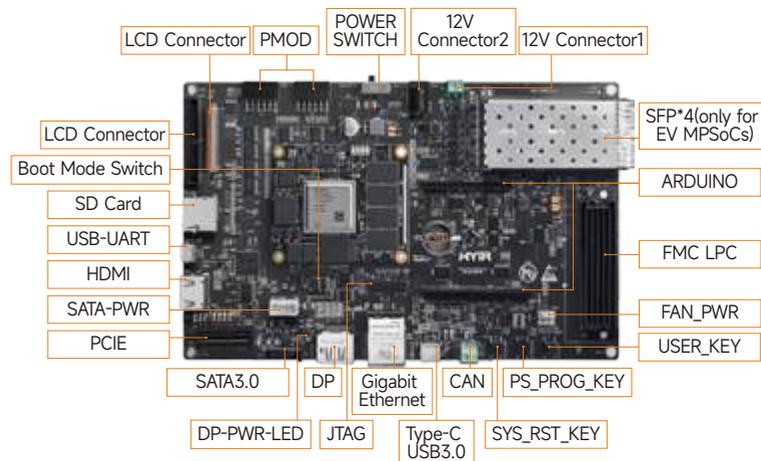
Medical Device



Industrial Control



Automotive



MYD-CZU3EG/4EV/5EV-V2 Development Board Top-view

AMD XILINX | MYC-CZU3EG-V3

- Zynq UltraScale+ ZU3EG, 4xA53@1.2GHz+2x Cortex-R5F@600MHz
- DDR4 SDRAM, eMMC, QSPI Flash
- USB 3.0, Gigabit Ethernet, CAN, TF, DP, PCIe, SATA, HDMI, LCD
- 60mm x 52mm; B2B Package, 2x160-pin; 0°C~+70°C Commercial; -40°C~+85°C Industrial
- Linux (PetaLinux)



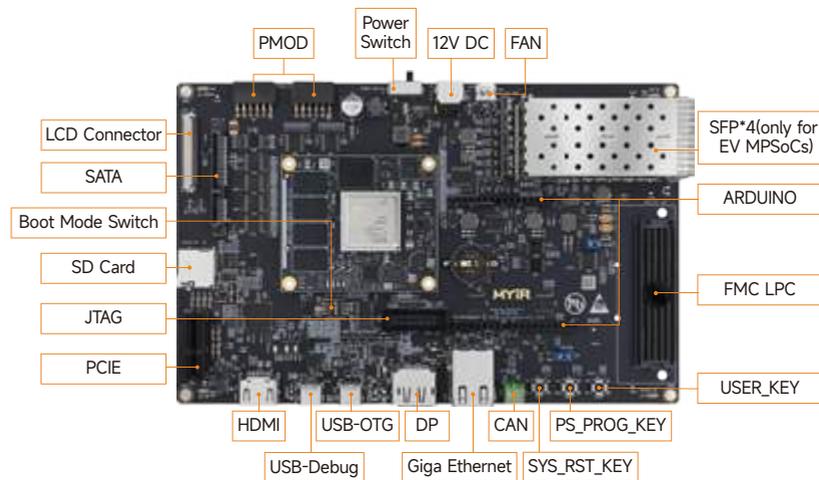
● **Part Selections** (Other Configurations can be Customized for Mass Production)

SOM Part Number	CPU	CPU Cores and Clock Speed (Max)	RAM	ROM	Others	Package	Working Temp.	Dimensions	Software	Development Board Part Number
MYC-CZU3EG-V3-8E4D-1200-C	XCZU3EG-1SFVC784	ARM:4*A53@1200MHz+2*R5F@533MHz + UltraScale+ FPGA 154K + Mali-400 MP2@667MHz	4GB DDR4	8GB eMMC	128MB QSPI Flash Ethernet PHY USB PHY	B2B 2x160PIN	0°C~+70°C	60mm × 52mm	Linux	MYD-CZU3EG-V3-8E4D-1200-C
-40°C~+85°C							MYD-CZU3EG-V3-8E4D-1200-I			

● **Peripherals/Interfaces**

Communications	2*ETH, 2*CAN 2.0B, 2*USB 2.0, 2*UART, 2*SPI, 2*I2C, 4*GTR
FPGA Expansion IO	156PIN FPGA HP IO (1.8V)

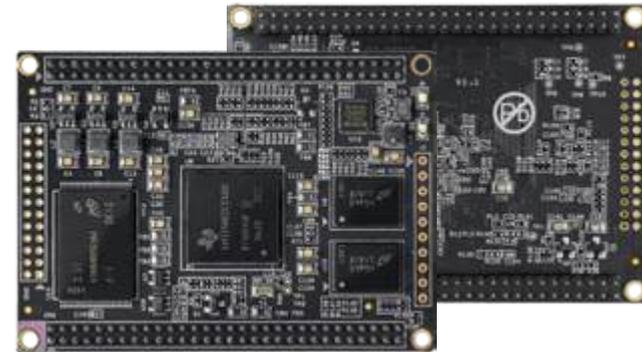
● **Key Applications**



MYD-CZU3EG-V3 Development Board Top-view

TEXAS INSTRUMENTS | MYC-C335X-V4

- Up to 1GHz TI AM335x Cortex-A8 processors
- DDR3, Nand Flash, Gigabit Ethernet PHY
- 6x UART, 2x USB2.0, 2x Gigabit Ethernet, 2x CAN
- 70mm x 50mm; DIP Package, 2x 60-pin; -40°C~+85°C Industrial; Linux



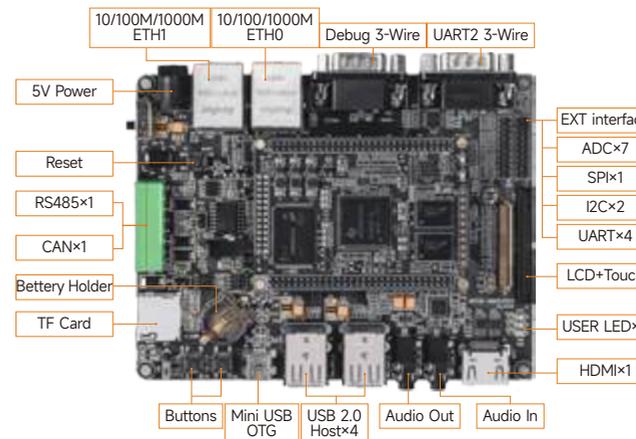
Part Selections (Other Configurations can be Customized for Mass Production)

SOM Part Number	CPU	CPU Cores and Clock Speed (Max)	RAM	ROM	Others	Package	Working Temp.	Dimensions	Software	Development Board Part Number
MYC-C3352-V4-256N256D-80-I	AM3352BZCZD80	Cortex-A8@800MHz	256MB DDR3	256MB Nand FLASH	Ethernet PHY 32Kbit EEPROM	DIP 2x60PIN	-40°C~+85°C	70mm × 50mm	Linux	MYD-C3352-V4-256N256D-80-I
MYC-C3352-V4-512N512D-80-I			512MB DDR3	512MB Nand FLASH			0°C~+70°C			MYD-C3352-V4-512N512D-80-I
MYC-C3352-V4-512N512D-80-C			256MB DDR3	256MB Nand FLASH			-40°C~+85°C			MYD-C3352-V4-512N512D-80-C
MYC-C3358-V4-256N256D-100-I	AM3358BZCZA100	Cortex-A8@1.0GHz	256MB DDR3	256MB Nand FLASH			0°C~+70°C			MYD-C3358-V4-256N256D-100-I
MYC-C3358-V4-512N512D-100-I			512MB DDR3	512MB Nand FLASH			-40°C~+85°C			MYD-C3358-V4-512N512D-100-I
MYC-C3358-V4-512N512D-100-C			512MB DDR3	512MB Nand FLASH			0°C~+70°C			MYD-C3358-V4-512N512D-100-C

Peripherals/Interfaces

Communications	2xRGMII, 2xCAN, 2xUSB2.0, 6xUART, 2xSPI, 3xI2C
Multimedia	RGB, 2xMcASP
Others	12bit 8ch ADC, JTAG

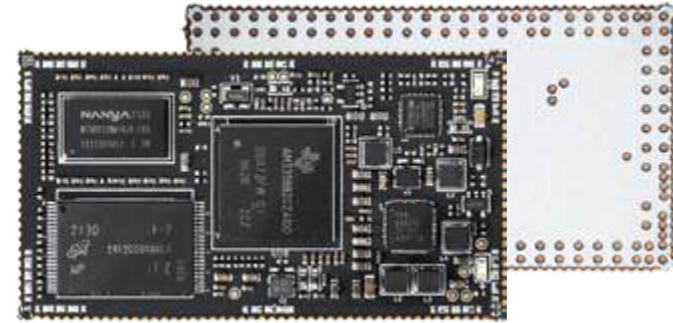
Key Applications



MYD-C335X-V4 Development Board Top-view

TEXAS INSTRUMENTS | MYC-Y335X-V2

- Up to 1GHz TI AM335x Cortex-A8 processors
- DDR3, Nand Flash, Gigabit Ethernet PHY, PMIC
- 6x UART, 2x USB 2.0, 2x Gigabit Ethernet, 2x CAN
- 65mm x 35mm; LCC Package, 146-pin; -40°C~+85°C Industrial; Linux



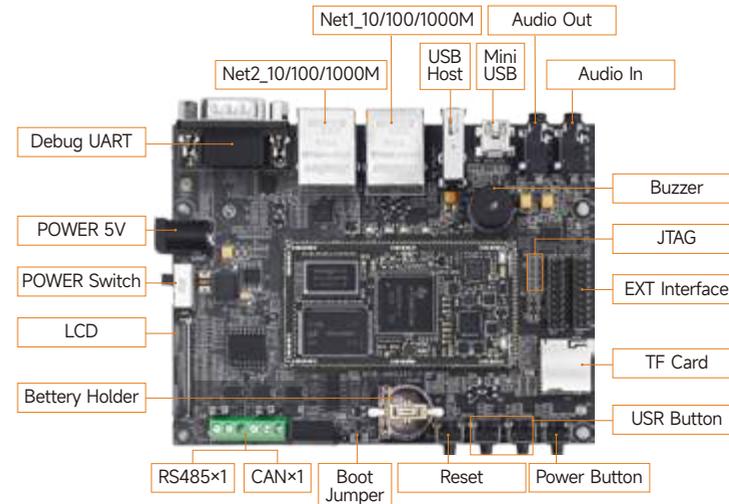
● **Part Selections** (Other Configurations can be Customized for Mass Production)

SOM Part Number	CPU	CPU Cores and Clock Speed (Max)	RAM	ROM	Others	Package	Working Temp.	Dimensions	Software	Development Board Part Number
MYC-Y3352-V2-256N256D-80-I	AM3352BZCZD80	Cortex-A8@800MHz	256MB DDR3	256MB Nand FLASH	Ethernet PHY 32Kbit EEPROM	LCC 146PIN	-40°C~+85°C	65mm x 35mm	Linux	MYD-Y3352-V2-256N256D-80-I
MYC-Y3358-V2-256N256D-100-I	AM3358BZCZA100	Cortex-A8@1.0GHz								MYD-Y3358-V2-256N256D-100-I

● **Peripherals/Interfaces**

Communications	2×RGMII, 2×CAN, 2×USB2.0, 6×UART, 2×SPI, 3×I2C
Multimedia	RGB, 2×McASP
Others	2×12bit 8ch ADC, JTAG

● **Key Applications**



MYD-Y335X-V2 Development Board Top-view

TEXAS INSTRUMENTS | MYC-J335X-V2

- Up to 1GHz TI AM335x Cortex-A8 processors
- DDR3, Nand Flash, Gigabit Ethernet PHY, PMIC
- 6x UART, 2x USB2.0, 2x Gigabit Ethernet, 2x CAN, 2x SPI
- 67mm x 45mm; MXM Package, 200-pin; -40°C~+85°C Industrial; Linux



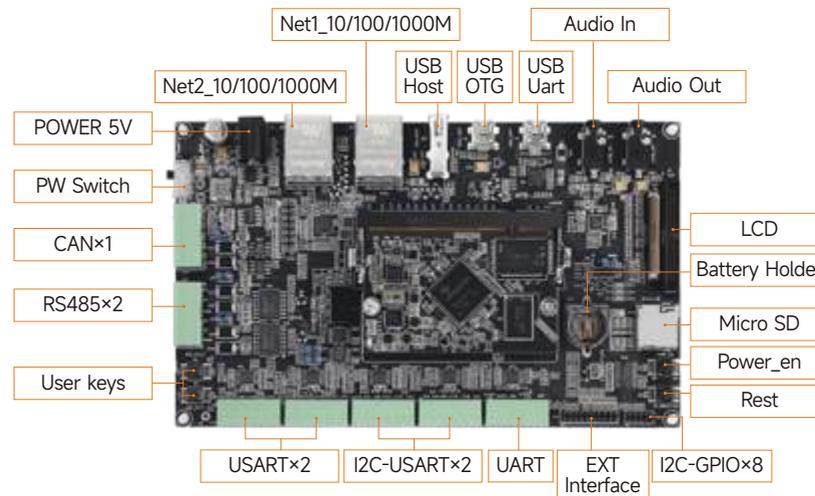
● **Part Selections** (Other Configurations can be Customized for Mass Production)

SOM Part Number	CPU	CPU Cores and Clock Speed (Max)	RAM	ROM	Others	Package	Working Temp.	Dimensions	Software	Development Board Part Number
MYC-J3352-V2-256N256D-80-I	AM3352BZCZD80	Cortex-A8@800MHz	256MB DDR3	256MB Nand FLASH	Ethernet PHY 32Kbit EEPROM	MXM 200PIN	-40°C~+85°C	67mm x 45mm	Linux	MYD-J3352-V2-256N256D-80-I
MYC-J3358-V2-256N256D-100-I	AM3358BZCZA100	Cortex-A8@1.0GHz								MYD-J3358-V2-256N256D-100-I

● **Peripherals/Interfaces**

Communications	2×RGMII, 2×CAN, 2×USB2.0, 6×UART, 2×SPI, 3×I2C
Multimedia	RGB, 2×McASP
Others	12bit 8ch ADC, JTAG

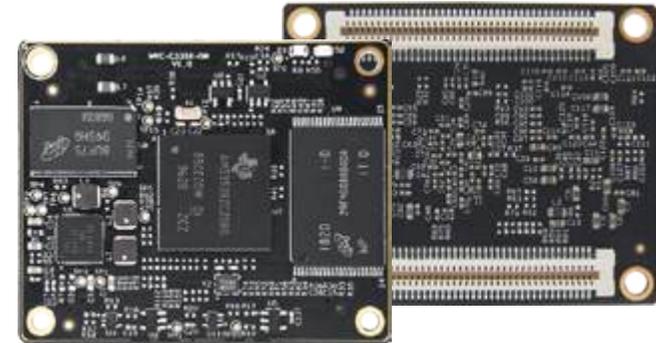
● **Key Applications**



MYD-J335X-V2 Development Board Top-view

TEXAS INSTRUMENTS | **MYC-C335X-GW**

- Up to 1GHz TI AM335x Cortex-A8 processors
- DDR3, Nand Flash/eMMC, EEPROM, PMIC
- 6x UART, 2x USB2.0, 2x Gigabit Ethernet, 2x CAN
- 50mm x 40mm; B2B Package, 2x 80-pin; -40°C~+85°C Industrial; Linux



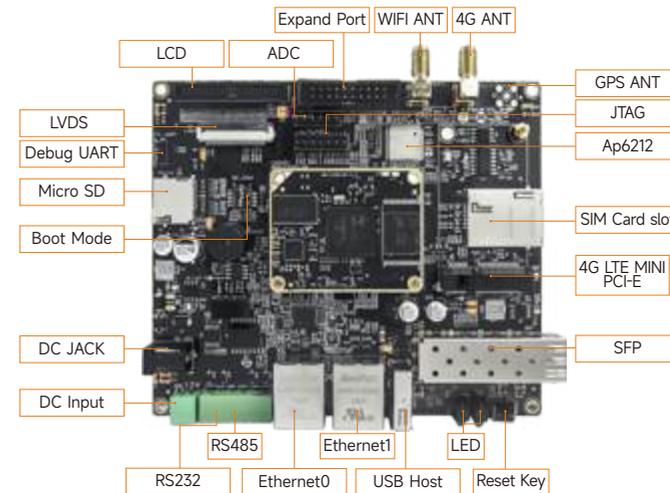
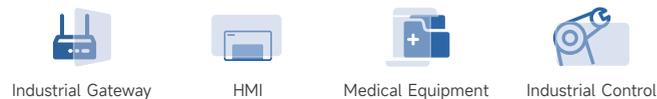
• **Part Selections** (Other Configurations can be Customized for Mass Production)

SOM Part Number	CPU	CPU Cores and Clock Speed (Max)	RAM	ROM	Others	Package	Working Temp.	Dimensions	Software	Development Board Part Number
MYC-C3354-256N256D-80-I-GW	AM3354BZCZD80	Cortex-A8@800MHz	256MB DDR3L	256MB Nand Flash	32kbit EEPROM	B2B 2x80PIN	-40°C~+85°C	50mm x 40mm	Linux	MYD-C3354-256N256D-80-I-GW
MYC-C3354-4E512D-80-I-GW			512MB DDR3L	4GB eMMC						MYD-C3354-4E512D-80-I-GW

• **Peripherals/Interfaces**

Communications	2xRGMII, 2xCAN, 2xUSB2.0, 6xUART, 2xSPI, 3xI2C
Multimedia	RGB, 2xMcASP
Others	12bit 8ch ADC, JTAG

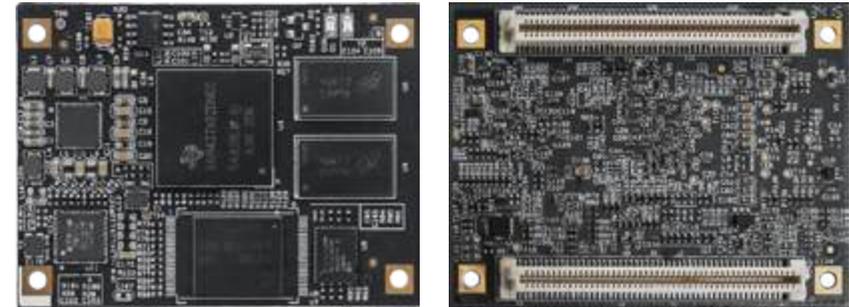
• **Key Applications**



MYD-C335X-GW Development Board Top-view

TEXAS INSTRUMENTS | **MYC-C437X-V2**

- Up to 1GHz TI AM437x Cortex-A9 Processor
- DDR3, eMMC, EEPROM, Gigabit Ethernet PHY, PMIC
- 6x UART, 2x USB2.0, 2x Gigabit Ethernet, 2x CAN, 2x SPI, 3x I2C, 2x Parallel Camera Interfaces
- 45mm x 60mm; B2B Package, 200-pin; -40°C~+85°C Industrial; Linux



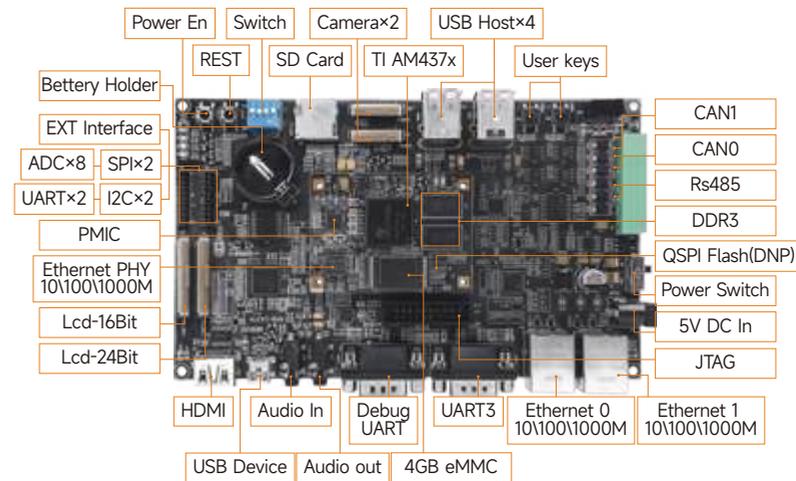
• **Part Selections** (Other Configurations can be Customized for Mass Production)

SOM Part Number	CPU	CPU Cores and Clock Speed (Max)	RAM	ROM	Others	Package	Working Temp.	Dimensions	Software	Development Board Part Number
MYC-C4378-V2-4E512D-100-C	AM4378BZDND100	Cortex-A9@1.0GHz	512MB DDR3	4GB eMMC	Ethernet PHY 32KB EEPROM	B2B 200PIN	0°C~+70°C	45mm x 60mm	Linux	MYD-C4378-V2-4E512D-100-C
MYC-C4378-V2-4E512D-100-I							-40°C~+85°C			MYD-C4378-V2-4E512D-100-I

• **Peripherals/Interfaces**

Communications	2×RGMII, 2×CAN, 2×USB2.0, 6×UART, 2×SPI, 3×I2C
Multimedia	RGB, 2×Parallel CSI, 2×McASP
Others	2×12bit 8ch ADC, JTAG

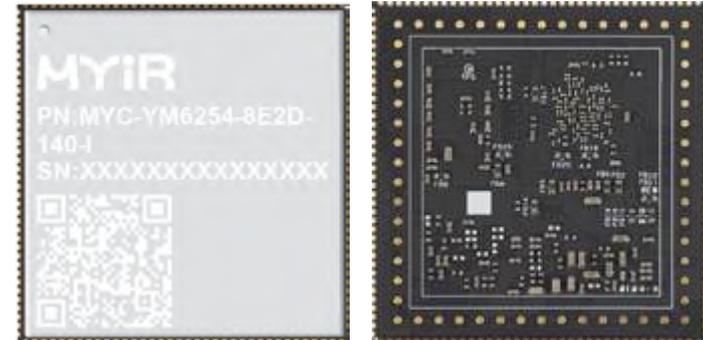
• **Key Applications**



MYD-C437X-V2 Development Board Top-view

TEXAS INSTRUMENTS | **MYC-YM62X**

- TI AM62x Processor, 1/2/4x Cortex-A53@1.4GHz + Cortex-M4F@400MHz
- DDR4, eMMC, EEPROM, PMIC
- 3D GPU (Only for AM625), full-HD dual-display support
- 2x Display Controllers, 2x USB2.0, 2x Gigabit Ethernet, 3x CAN-FD, 1x GPMC
- 43mm x 45mm; LCC + LGA Package, 164-pin + 58-pin; -40°C~+85°C Industrial; Linux



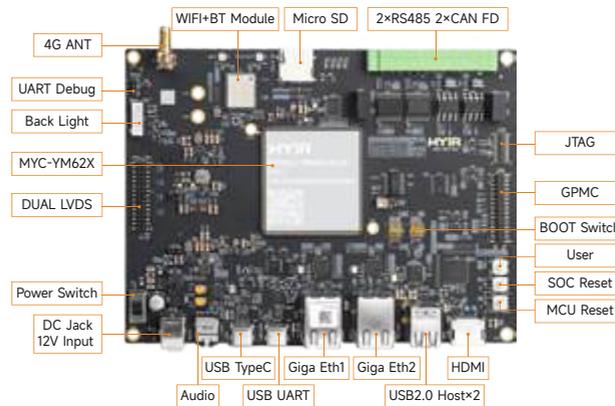
• **Part Selections** (Other Configurations can be Customized for Mass Production)

SOM Part Number	CPU	CPU Cores and Clock Speed (Max)	RAM	ROM	Others	Package	Working Temp.	Dimensions	Software	Development Board Part Number
MYC-YM6254-8E2D-140-I	AM6254ATCGGAALW	4xCortex-A53@1.4GHz+ Cortex-M4F@400MHz	2GB DDR4	8GB eMMC	32Kbit EEPROM	LCC+LGA 222PIN	-40°C~+85°C	43mm x 45mm	Linux	MYD-YM6254-8E2D-140-I
MYC-YM6252-8E1D-140-I	AM6252ATCGGAALW	2xCortex-A53@1.4GHz+ Cortex-M4F@400MHz	1GB DDR4							MYD-YM6252-8E1D-140-I
MYC-YM6231-8E1D-140-I	AM6231ASGGAALW	Cortex-A53@1.0GHz+ Cortex-M4F@400MHz	1GB DDR4							MYD-YM6231-8E1D-140-I

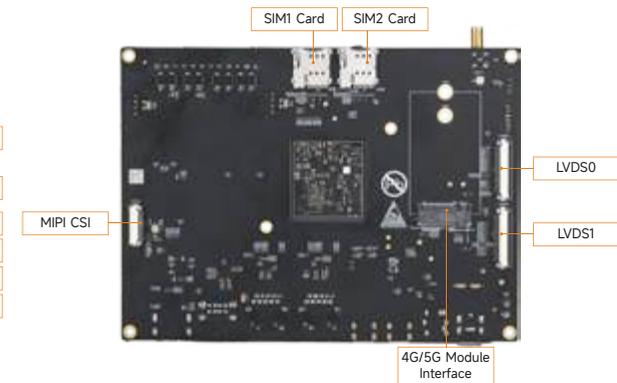
• **Peripherals/Interfaces**

Communications	2xRGMII, 2xUSB 2.0, 9xURAT, 3xCAN FD, 4xI2C, 5xSPI
Multimedia	2xLVDS, 1xRGB, 1xMIPI CSI, 3xMCASP
Others	1xGPMC, 1xJTAG

• **Key Applications**



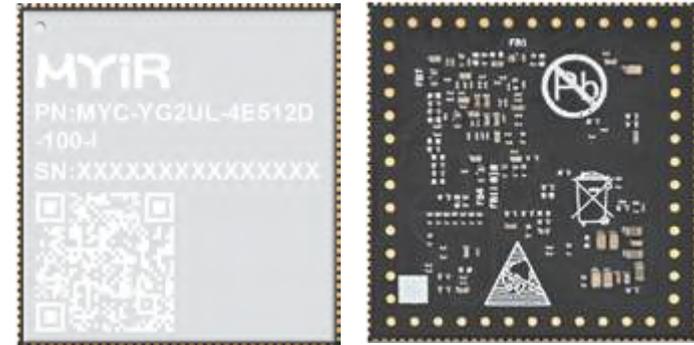
MYD-YM62X Development Board Top-view



MYD-YM62X Development Board Bottom-view

RENESAS | MYC-YG2UL

- RENESAS RZ/G2UL Processor, 64-bit MPU, Cortex-A55@1.0GHz + Cortex-M33@200MHz
- DDR3L, eMMC, EEPROM
- Camera Interface, Display Interface, USB2.0, CAN-FD, Dual Gigabit Ethernet
- 37mm x 39mm; LCC + LGA Package, 190-pin; -40°C~+85°C Industrial; Linux OS



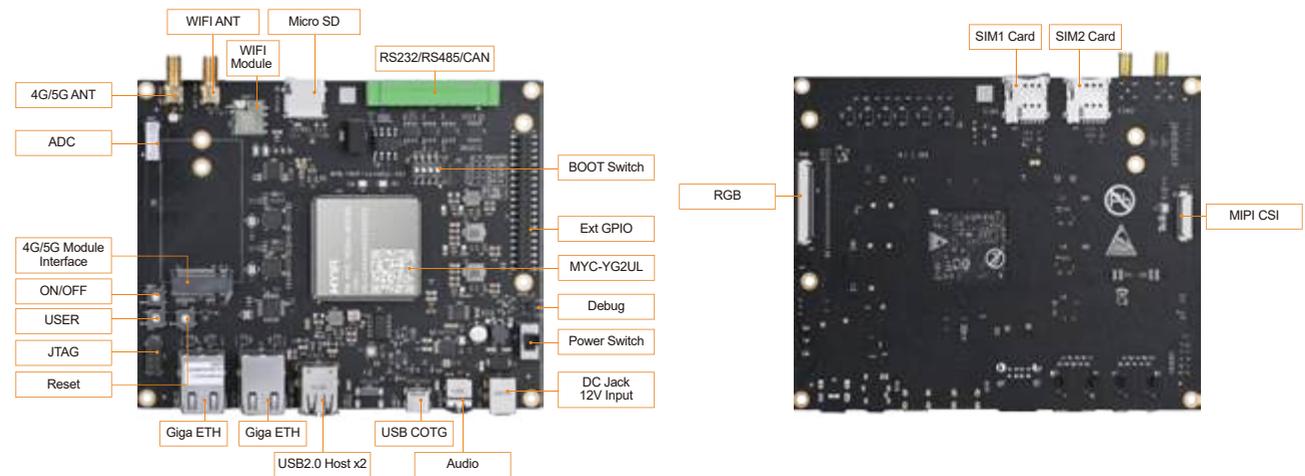
● **Part Selections** (Other Configurations can be Customized for Mass Production)

SOM Part Number	CPU	CPU Cores and Clock Speed (Max)	RAM	ROM	Others	Package	Working Temp.	Dimensions	Software	Development Board Part Number
MYC-YG2UL-4E512D-100-I	R9A07G043U11GBG	Cortex-A55@1.0GHz+ Cortex-M33@200MHz	512MB DDR3	4GB eMMC	32KBit EEPROM	LCC+LGA 190PIN	-40°C~+85°C	37mm x 39mm	Linux OpenWrt	MYD-YG2UL-4E512D-100-I

● **Peripherals/Interfaces**

Communications	2×RGMII, 2×CAN FD, 2×USB2.0, 7×UART, 3×SPI, 4×I2C
Multimedia	RGB, MIPI CSI, 4×SSI
Others	12-bit 2-ch ADC, JTAG

● **Key Applications**

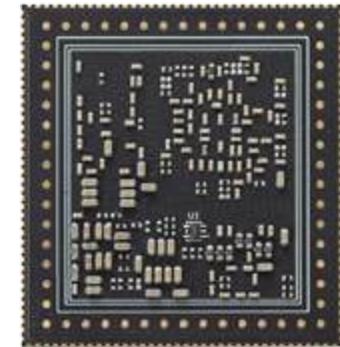


MYD-YG2UL Development Board Top-view

MYD-YG2UL Development Board Bottom-view

RENESAS | MYC-YG2LX

- RENESAS RZ/G2L Processor, 2x Cortex-A55@1.2GHz + Cortex-M33@200MHz
- Integrated 3D Graphics engine and video CODEC engine (H.264)
- Rich Multimedia Interfaces: MIPI-DSI / RGB / MIPI-CSI / Parallel CSI
- 43mm x 45mm; LCC + LGA Package, 222-pin; -40°C~+85°C Industrial; Linux / Ubuntu OS



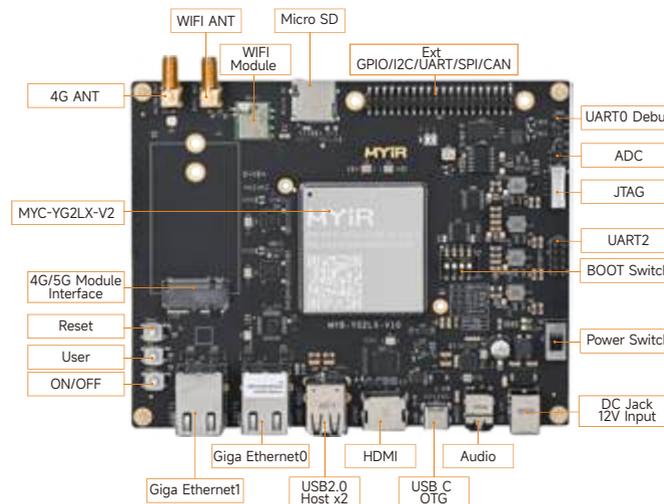
Part Selections (Other Configurations can be Customized for Mass Production)

SOM Part Number	CPU	CPU Cores and Clock Speed (Max)	RAM	ROM	Others	Package	Working Temp.	Dimensions	Software	Development Board Part Number
MYC-YG2L23-8E1D-120-I	R9A07G044L23GBG	2xCortex-A55@1.2GHz+ Cortex-M33@200MHz	1GB DDR4	8GB eMMC	32KB EEPROM	LCC+LGA 222PIN	-40°C~+85°C	43mm x 45mm	Linux Ubuntu	MYD-YG2L23-8E1D-120-I
MYC-YG2L23-8E2D-120-I			2GB DDR4							MYD-YG2L23-8E2D-120-I

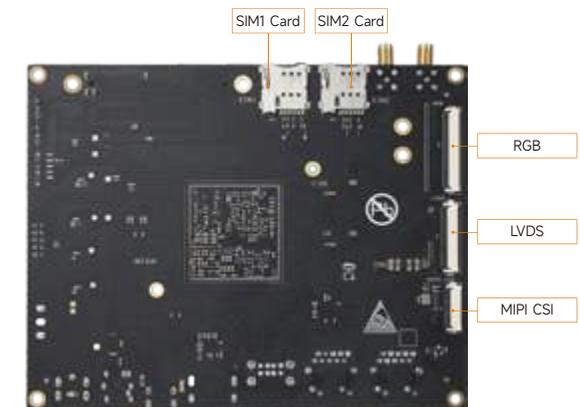
Peripherals/Interfaces

Communications	2×RGMII, 2×CAN FD, 2×USB2.0, 7×UART, 3×SPI, 4×I2C
Multimedia	RGB, MIPI DSI, Parallel CSI, MIPI CSI, SSI, SRC
Others	12-bit 8-ch ADC, JTAG

Key Applications



MYD-YG2LX Development Board Top-view



MYD-YG2LX Development Board Bottom-view

ALLWINNER | MYC-YT113i

- Allwinner T113-i Processor, 2x Cortex-A7@1.2GHz + RISC-V@800MHz
- DDR3, eMMC, EEPROM
- 1x Gigabit Ethernet, 2x USB2.0, 6x UART, 2x CAN, 8x PWM, 1x GPADC, 4x TPADC
- 37mm x 39mm; LCC + LGA Package, 140-pin + 50-pin; -40°C~+85°C Industrial; Linux



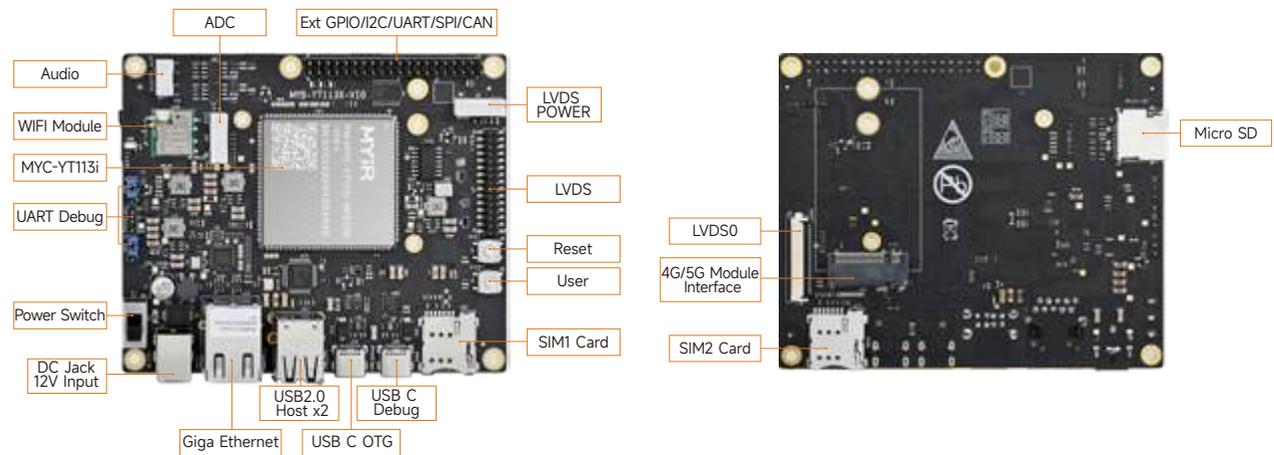
● **Part Selections** (Other Configurations can be Customized for Mass Production)

SOM Part Number	CPU	CPU Cores and Clock Speed (Max)	RAM	ROM	Others	Package	Working Temp.	Dimensions	Software	Development Board Part Number
MYC-YT113i-4E256D-110-I	T113-i	2xCortex-A7@1.2G +RISC-V@800MHz	256MB DDR3	4GB eMMC	32Kbit EEPROM	LCC+LGA 140+50PIN	-40°C~+85°C	37mm x 39mm	Linux	MYD-YT113i-4E256D-110-I
MYC-YT113i-4E512D-110-I			512MB DDR3							MYD-YT113i-4E512D-110-I
MYC-YT113i-8E512D-110-I			1GB DDR3	8GB eMMC						MYD-YT113i-8E512D-110-I
MYC-YT113i-8E1D-110-I				1GB DDR3						MYD-YT113i-8E1D-110-I

● **Peripherals/Interfaces**

Communications	RGMII, 2xUSB2.0, 6xUART, 2xCAN, SDIO, SPI, 4xI2C, 8xPWM
Multimedia	MIPI DSI, RGB DSI, Dual link LVDS, CVBS OUT, Parallel CSI, 2xI2S

● **Key Applications**



MYD-YT113i Development Board Top-view

MYD-YT113i Development Board Bottom-view

ALLWINNER | MYC-YT113X

- Allwinner T113-S3 Processor, 2x Cortex-A7@1.2GHz, with built-in 128MB DDR3
- Rich multimedia interfaces: MIPI-DSI / RGB / LVDS / Parallel CSI
- 6x UART, 2x USB2.0, 1x Gigabit Ethernet, 2x CAN
- 37mm x 39mm; LCC Package, 140-pin; -40°C~+85°C Industrial; Linux



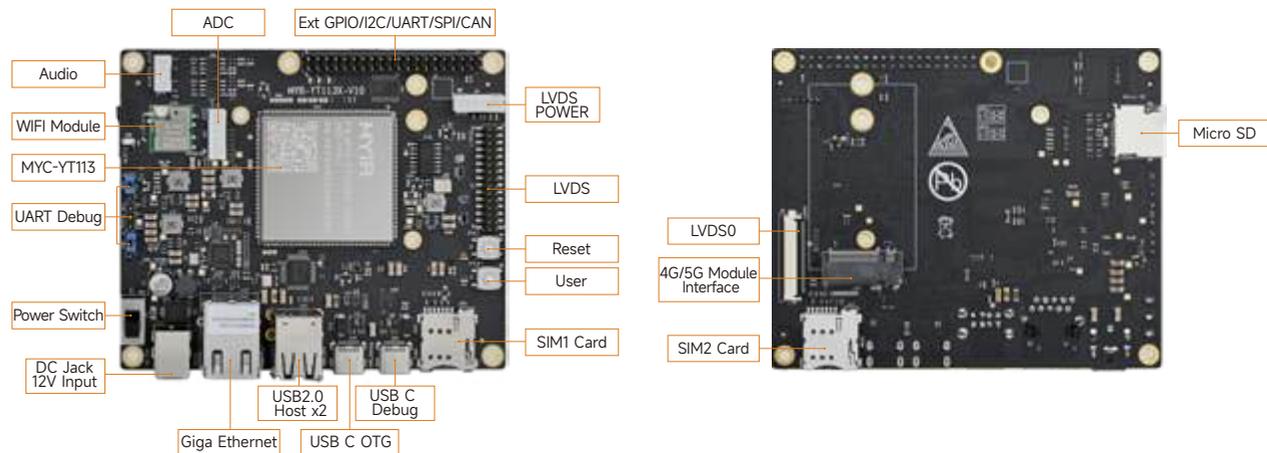
● **Part Selections** (Other Configurations can be Customized for Mass Production)

SOM Part Number	CPU	CPU Cores and Clock Speed (Max)	RAM	ROM	Others	Package	Working Temp.	Dimensions	Software	Development Board Part Number
MYC-YT113S3-256N128D-110-I	T113-S3	2xCortex-A7@1.2GHz	128MB DDR3	256MB Nand Flash	32Kbit EEPROM	LCC 140PIN	-40°C~+85°C	37mm x 39mm	Linux	MYD-YT113S3-256N128D-110-I
MYC-YT113S3-4E128D-110-I				4GB eMMC						MYD-YT113S3-4E128D-110-I

● **Peripherals/Interfaces**

Communications	RGMII, 2xUSB2.0, 6xUART, 2xCAN, SDIO, 2xSPI, 4xI2C, 8xPWM
Multimedia	MIPI DSI, RGB DSI, 2xLVDS, Parallel CSI, 2xI2S

● **Key Applications**



MYD-YT113X Development Board Top-view

MYD-YT113X Development Board Bottom-view

ALLWINNER | MYC-LT536

- Allwinner T536 processor, 4x Cortex-A55@1.6GHz + RISC-V@600MHz
- LPDDR4, eMMC, EEPROM, PMIC
- 2 Tops NPU (T536MX-CEN2), Graphic 2D, 4K HD Video Codec
- 43mm x 45mm; LGA Package, 381-pin; -40°C~+85°C Industrial; Linux



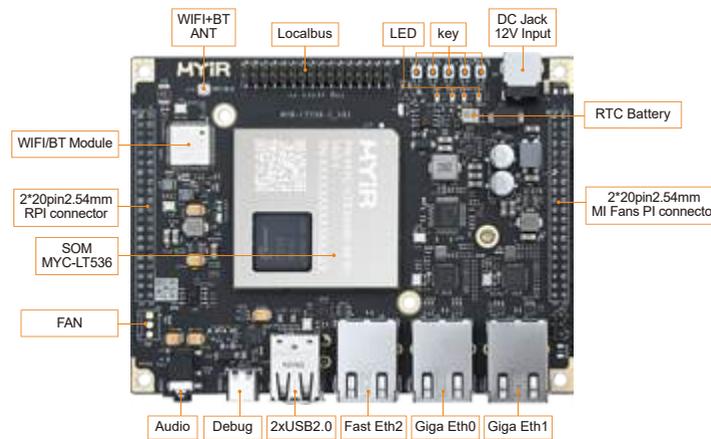
● **Part Selections** (Other Configurations can be Customized for Mass Production)

SOM Part Number	CPU	CPU Cores and Clock Speed (Max)	RAM	ROM	Others	Package	Working Temp.	Dimensions	Software	Development Board Part Number
MYC-LT536ME-8E1D-160-I	T507H	4xCortex-A55@1.6GHz+ RISC-V@600MHz	1GB LPDDR4X	8GB eMMC	32Kbit EEPROM	LGA 381PIN	-40°C~+85°C	43mm x 45mm	Linux	MYD-LT536ME-8E1D-160-I-GK
MYC-LT536ME-16E2D-160-I			2GB LPDDR4X	16GB eMMC						MYD-LT536ME-16E2D-160-I-GK
MYC-LT536MN2-32E4D-160-I	T536MX-CEX	4xCortex-A55@1.6GHz+ RISC-V@600MHz, 2Tops NPU	4GB LPDDR4X	32GB eMMC						MYD-LT536MN2-32E4D-160-I-GK

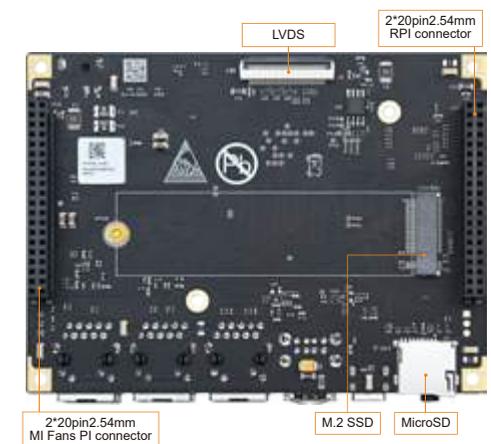
● **Peripherals/Interfaces**

Communications	2xRGMII, USB3.1 DRD/PCIE2.0, 2xUSB2.0, Localbus 4xCAN FD, 17xUART
Multimedia	LVDS, MIPI DSI, Parallel DSI, 4xI2S
Others	9xI2C, 34xPWM, 6xSPI, SDIO, 26x12bit GPADC

● **Key Applications**



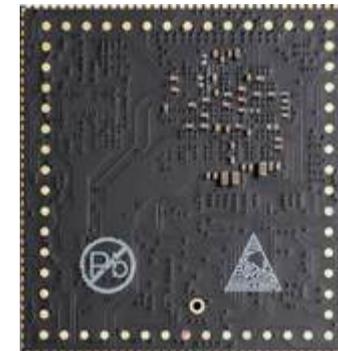
MYD-LT536 Development Board Top-view



MYD-LT536 Development Board Bottom-view

ALLWINNER | MYC-YT507H

- Allwinner T507-H processor, 4x Cortex-A53@1.5GHz
- LPDDR4, eMMC, EEPROM, PMIC
- Supports 4K@60FPS H.265 video decoding and 4K@25FPS H.264 video encoding
- Supports different display in dual screens, MIPI CSI and DVP camera inputs
- 43mm x 45mm; LCC + LGA Package, 164-pin + 58-pin; -40°C~+85°C Industrial; Linux / Android / Ubuntu



• **Part Selections** (Other Configurations can be Customized for Mass Production)

SOM Part Number	CPU	CPU Cores and Clock Speed (Max)	RAM	ROM	Others	Package	Working Temp.	Dimensions	Software	Development Board Part Number
MYC-YT507H-8E1D-150-I	T507-H	4xCortex-A53@1.5GHz	1GB LPDDR4	8GB eMMC	32Kbit EEPROM	LCC+LGA 222PIN	-40°C~+85°C	43mm x 45mm	Linux Android Ubuntu	MYD-YT507H-8E1D-150-I
MYC-YT507H-8E2D-150-I			2GB LPDDR4							MYD-YT507H-8E2D-150-I

• **Peripherals/Interfaces**

Communications	RGMII, 4xUSB2.0, 6xUART, 2xSDIO, 2xSPI, 4xI2C, 6xPWM, 5xADC
Multimedia	HDMI, 2xLVDS, RGB24, TV CVBS, Parallel CSI, MIPI CSI, 3xI2S, SPDIF

• **Key Applications**



Commercial Display



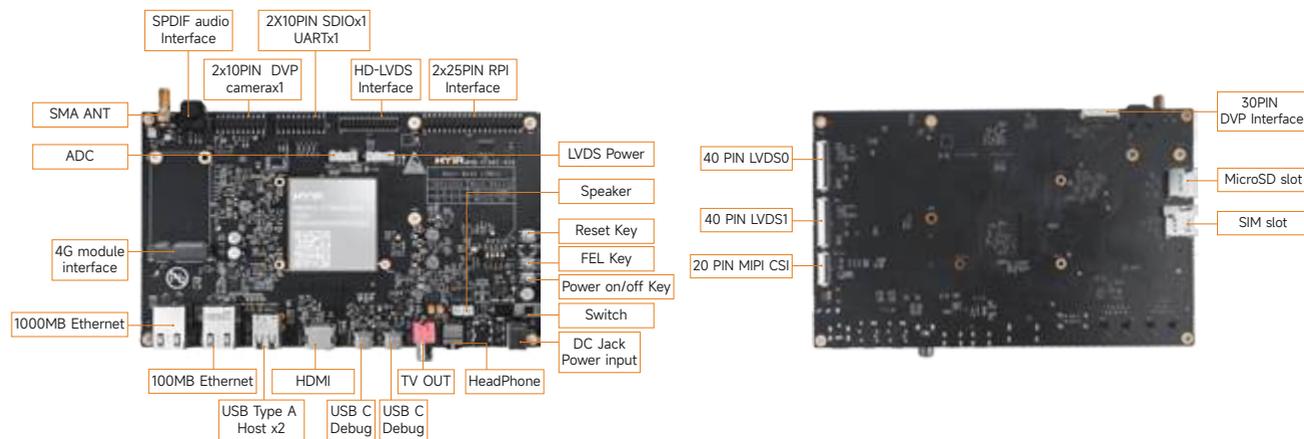
Medical Equipment



Industrial Control



Intelligent Terminal

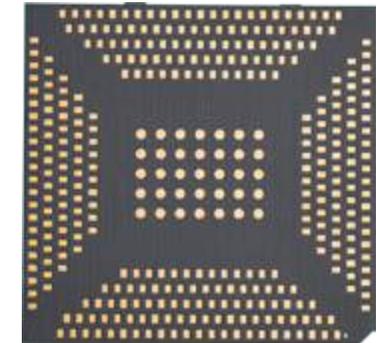


MYD-YT507H Development Board Top-view

MYD-YT507H Development Board Bottom-view

ALLWINNER | MYC-LT527

- Allwinner T527 processor, 4x Cortex-A55@1.8GHz + 4x Cortex-A55@1.4GHz + RISC-V@200MHz
- Up to 2 Tops NPU, LPDDR4, eMMC, EEPROM, PMIC
- G57 GPU, 4K encoding/decoding VPU, HiFi4 DSP, 4 to 6 camera inputs
- Multi video output interfaces: HDMI, DP, LVDS, MIPI-DSI, and RGB; Supports 4K+1080P dual-screen display
- 43mm x 45mm; LGA Package, 381-pin; -40°C~+85°C Industrial; Linux / Android / Ubuntu



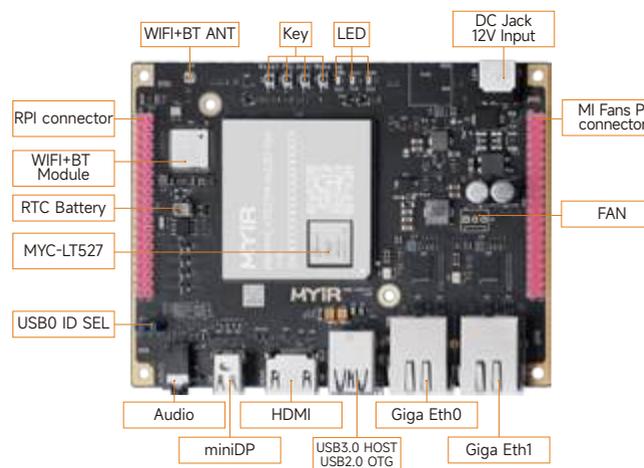
Part Selections (Other Configurations can be Customized for Mass Production)

SOM Part Number	CPU	CPU Cores and Clock Speed (Max)	RAM	ROM	Others	Package	Working Temp.	Dimensions	Software	Development Board Part Number
MYC- LT527MN-16E2D-180-I-G	T527MN	4xCortex-A55@1.8GHz +4xCortex-A55@1.4GHz, RISC-V@200MHz, HiFi4 600MHz, 2Tops NPU	2GB LPDDR4	16GB eMMC	32kbit EEPROM	LGA 381PIN	-40°C~+85°C	43mm x 45mm	Linux Android Ubuntu	MYD- LT527MN-16E2D-180-I
MYC- LT527MN-32E4D-180-I-G			4GB LPDDR4	32GB eMMC						MYD- LT527MN-32E4D-180-I
MYC- LT527M-16E2D-180-I-G	T527M	4xCortex-A55@1.8GHz +4xCortex-A55@1.4GHz, RISC-V@200MHz	2GB LPDDR4	16GB eMMC			MYD- LT527M-16E2D-180-I			
MYC- LT527M-16E2D-180-E							-20°C~+70°C			MYD- LT527M-16E2D-180-E

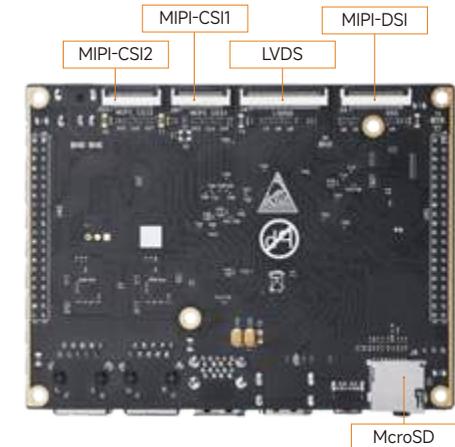
Peripherals/Interfaces

Communications	RGMII, 4xUSB2.0, 6xUART, 2xSDIO, 2xSPI, 4xI2C, 6xPWM, 5xADC
Multimedia	HDMI, 2xLVDS, RGB24, TV CVBS, Parallel CSI, MIPI CSI, 3xI2S, SPDIF

Key Applications



MYD-LT527 Development Board Top-view



MYD-LT527 Development Board Bottom-view

芯驰 SemiDrive | MYC-JD9360

- SemiDrive D9-Pro processor, 6x Cortex-A55@1.6GHz + Cortex-R5@800MHz + 0.8 Tops NPU
- Support dual display at 1080p resolution of different contents
- Support the third HMI display through Cortex-R5 co-processor control
- HD vision processing unit (VPU): H.264 encoding and decoding 4Kp30, H.265 decoding 4Kp30
- 82mm x 45mm; MXM Package, 314-pin; -40°C~+85°C Industrial; Linux / Ubuntu



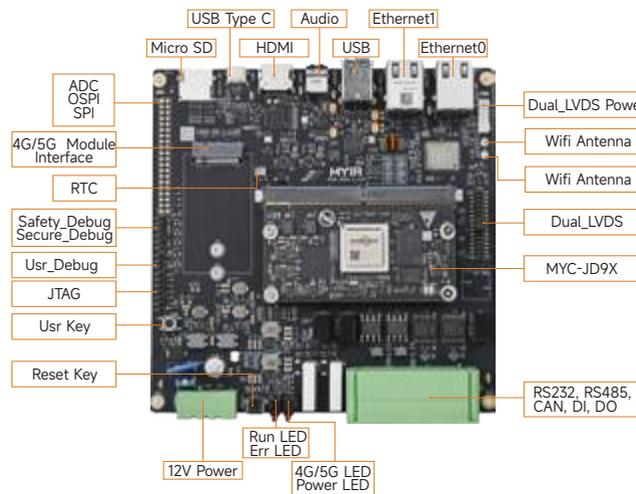
● **Part Selections** (Other Configurations can be Customized for Mass Production)

SOM Part Number	CPU	CPU Cores and Clock Speed (Max)	RAM	ROM	Others	Package	Working Temp.	Dimensions	Software	Development Board Part Number
MYC-JD9360-16E2D-160-I	D9-Pro	6xCortex-A55@1.6GHz +Cortex-R5@800MHz +0.8Tops NPU	2GB LPDDR4	16GB eMMC	EEPROM	MXM 314PIN	-40°C~+85°C	82mm × 45mm	Linux Ubuntu	MYD-JD9360-16E2D-160-I

● **Peripherals/Interfaces**

Communications	2×RGMI, 2×USB3.0, 2×PCIe3.0, 16×UART, 4×CAN FD, 2×SDIO, 8×SPI, 12×I2C, 8×PWM, 4×ADC
Multimedia	MIPI DSI, LVDS, MIPI CSI, Parallel CSI

● **Key Applications**



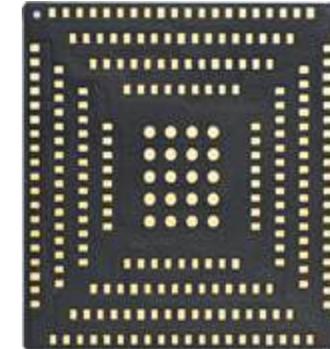
MYD-JD9360 Development Board Top-view



MYD-JD9360 Development Board Bottom-view

nuvoTon | MYC-LMA35

- Nuvoton NuMicro MA35D1 with Stacked 256MB DDR3L, 2x Cortex-A35@800MHz + Cortex-M4@180MHz
- Nand Flash / eMMC, EEPROM
- 4x CAN FD, 17x UART, 2x I2S, 6x I2C, 8x EADC, 1x JTAG, 1x RGB, 2x Parallel CSI, 18x EPWM, 4x SPI
- 2D Graphic Engine (GFX), LCD display controller with the resolution up to 1080p@60 FPS
- 37mm x 39mm; LGA Package, 252-pin; -40°C~+85°C Industrial; Linux / Debian



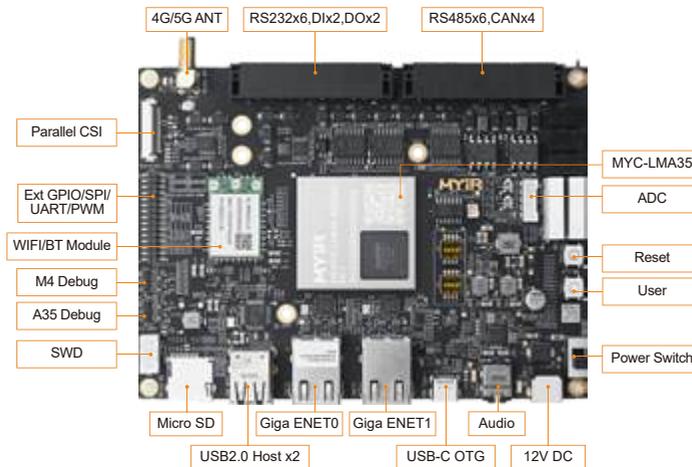
● **Part Selections** (Other Configurations can be Customized for Mass Production)

SOM Part Number	CPU	CPU Cores and Clock Speed (Max)	RAM	ROM	Others	Package	Working Temp.	Dimensions	Software	Development Board Part Number
MYC-LMA35-256N256D-80-I	MA35D16A887C	2xCortex-A35@800MHz +Cortex-M4@180MHz	256MB DDR3L	256MB Nand Flash	32Kbit EEPROM	LGA 252PIN	-40°C~+85°C	37mm × 39mm	Linux Debian	MYD-LMA35-256N256D-80-I
MYC-LMA35-8E256D-80-I				8GB eMMC						MYD-LMA35-8E256D-80-I
MYC-LMA35-8E512D-80-I	MA35D16AJ87C	512MB DDR3L	MYD-LMA35-8E512D-80-I							

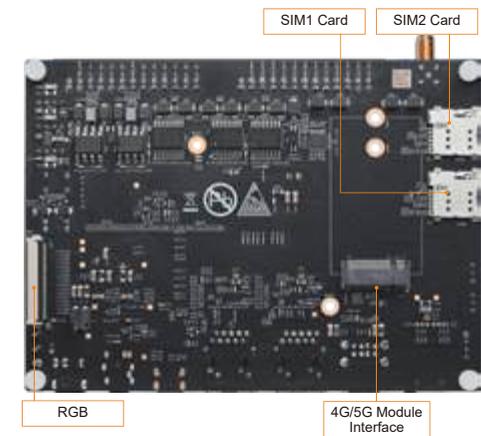
● **Peripherals/Interfaces**

Communications	2×RGMII, 2×USB 2.0, 4×CAN FD, 17×UART, 4×SPI, 6×I2C, SDIO 3.0
Multimedia	1×RGB, 2×Parallel CSI, 2×I2S
Others	8×EADC, 1×JTAG, 18×EPWM

● **Key Applications**



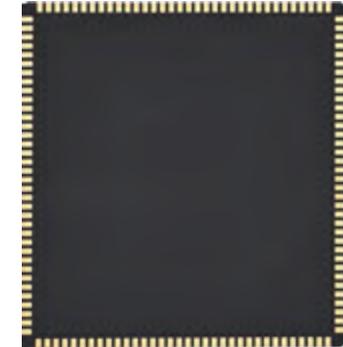
MYD-LMA35 Development Board Top-view



MYD-LMA35 Development Board Bottom-view

Rockchip | MYC-YR3506

- Rockchip RK3506 processor, 3x Cortex-A7@up to 1.5GHz + Cortex-M0@200MHz
- LPDDR3L, Nand Flash/eMMC, EEPROM
- 2x 10/100Mbps Ethernet, 2x CAN, 6x UART, 2x USB2.0, 3x SPI, 3x I2C, 12x PWM
- 37mm x 39mm; LCC Package, 140-pin; 0°C~+70°C Commercial or -40°C~+85°C Industrial; Linux



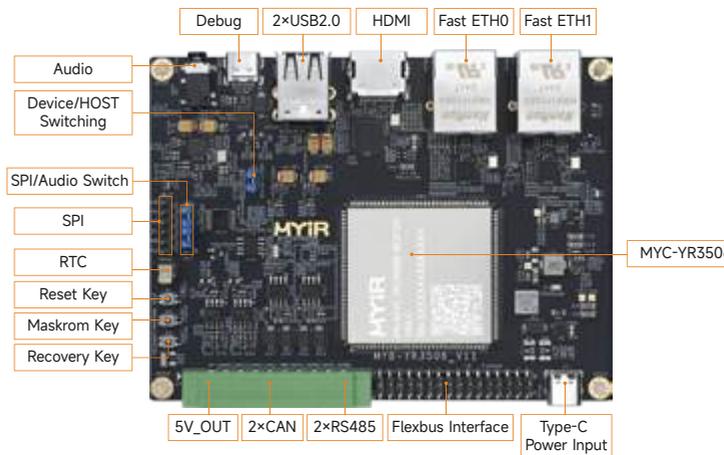
● **Part Selections** (Other Configurations can be Customized for Mass Production)

SOM Part Number	CPU	CPU Cores and Clock Speed (Max)	RAM	ROM	Others	Package	Working Temp.	Dimensions	Software	Development Board Part Number
MYC-YR3506B-8E512D-150-C	RK3506B	3xCortex-A7@1.5GHz + Cortex-M0@200MHz	512MB LPDDR3L	8GB eMMC	32Kbit EEPROM	LCC 140PIN	0°C~+70°C	37mm x 39mm	Linux	MYD-YR3506B-256N256D-150-C
MYC-YR3506B-256N256D-150-C				256MB Nand Flash						MYD-YR3506B-256N256D-150-C
MYC-YR3506J-256N256D-120-I	RK3506J	3xCortex-A7@1.2GHz + Cortex-M0@200MHz	256MB LPDDR3L	256MB Nand Flash	32Kbit EEPROM	LCC 140PIN	-40°C~+85°C	37mm x 39mm	Linux	MYD-YR3506J-256N8E256D-120-I
MYC-YR3506J-256N8E256D-120-I				8GB eMMC						MYD-YR3506J-256N8E256D-120-I

● **Peripherals/Interfaces**

Communications	2xRMII, 2xUSB 2.0, 2xCAN, 6xUART, 3xSPI, 3xI2C
Multimedia	1xRGB, 2xMIPI-CSI, 1xMIPI-DSI
Others	1xSARADC, 12xPWM

● **Key Applications**



MYD-YR3506 Development Board Top-view



MYD-YR3506 Development Board Bottom-view

Rockchip | MYC-YR3562

- Rockchip RK3562 processor, 4x Cortex-A53@up to 2.0GHz + MCU@200MHz
- LPDDR4, eMMC, EEPROM
- GPU G52, VPU 4K@30fps Decoder, 1080p@60fps Encoder, NPU 1Tops (RK3562)
- 2x 10/100Mbps Ethernet, 1x Gigabit Ethernet, PCIE/USB3.0, 2x CAN (RK3562J), 10x UART
- 43mm x 45mm; LCC + LGA Package, 222-pin; 0°C~+70°C Commercial or -40°C~+85°C Industrial; Linux



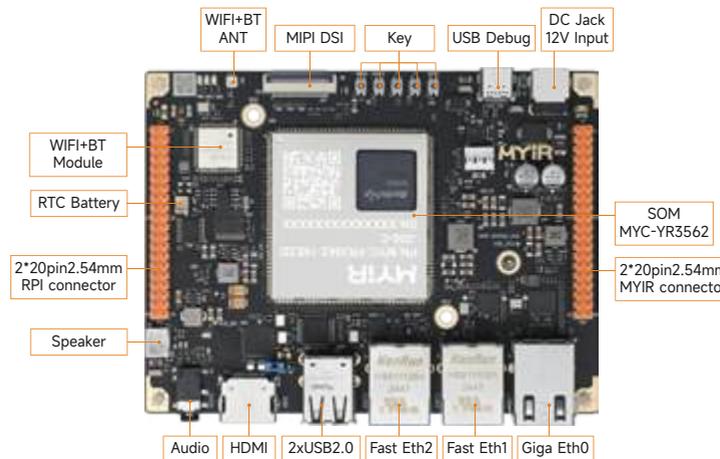
● **Part Selections** (Other Configurations can be Customized for Mass Production)

SOM Part Number	CPU	CPU Cores and Clock Speed (Max)	RAM	ROM	Others	Package	Working Temp.	Dimensions	Software	Development Board Part Number
MYC-YR3562J-8E1D-180-I	RK3562J	4xCortex-A53@1.8GHz + MCU@200MHz, 2xCAN	1GB LPDDR4	8GB eMMC	32KBit EEPROM	LCC 164pin + LGA 58pin	-40°C~+85°C	43mm x 45mm	Linux	
MYC-YR3562J-16E2D-180-I			2GB LPDDR4	16GB eMMC						MYD-YR3562J-16E2D-180-I-GK
MYC-YR3562-16E2D-200-C	RK3562	4xCortex-A53@2.0GHz + MCU@200MHz, 1Tops NPU					0°C~+70°C			MYD-YR3562-16E2D-200-C

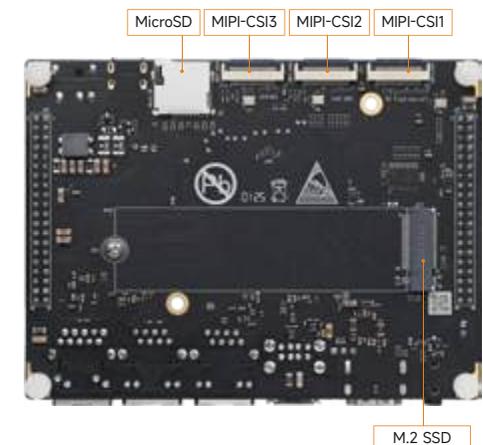
● **Peripherals/Interfaces**

Communications	RGMI+RMII, SDIO, USB3.0/PCIE2.1, USB2.0, 10xUART, 2xCAN (RK3562J)
Multimedia	LVDS, MIPI DSI, Parallel DSI, 3xI2S
Others	6xI2C, 16xPWM, 3xSPI, 26x10bit SARADC

● **Key Applications**



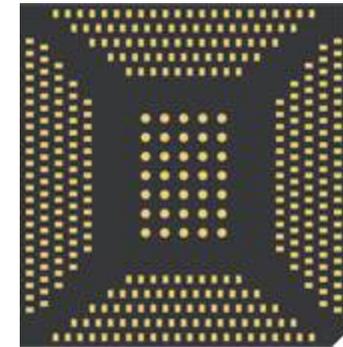
MYD-YR3562 Development Board Top-view



MYD-YR3562 Development Board Bottom-view

Rockchip | MYC-LR3568

- Rockchip RK3568 processor, 4x Cortex-A55@up to 2.0GHz + 1 Tops NPU
- LPDDR4, eMMC, EEPROM
- Supports 4K 60fps H.265/H.264/VP9 Decoder and 1080P 60fps H.265/H.264 Encoder
- Arm Mali-G52 2EE GPU with support for OpenGL ES 1.1/2.0/3.2, OpenCL 2.0, Vulkan 1.1
- 43mm x 45mm; LGA Package, 381-pin; -40°C~+85°C Industrial or -20°C~+70°C Extended
- Support Linux, Debian, Ubuntu, Android



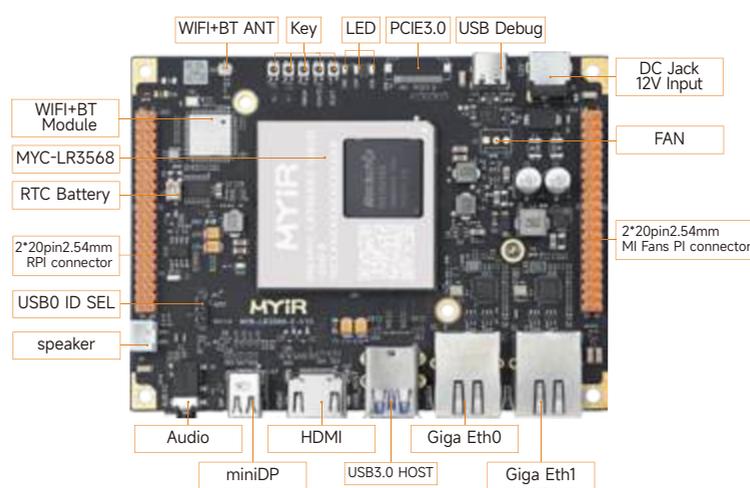
● **Part Selections** (Other Configurations can be Customized for Mass Production)

SOM Part Number	CPU	CPU Cores and Clock Speed (Max)	RAM	ROM	Others	Package	Working Temp.	Dimensions	Software	Development Board Part Number
MYC-LR3568J-16E2D-180-I	RK3568J	4xCortex-A55@1.4GHz	2GB DDR4	16GB eMMC	32KB EEPROM	LGA 381PIN	-40°C~+85°C	43mm × 45mm	Linux Debian Ubuntu Android	MYD-LR3568J-16E2D-180-I-GK
MYC-LR3568B2-16E2D-200-E	RK3568B2	4xCortex-A55@2.0GHz					-20°C~+70°C			MYD-LR3568B2-16E2D-200-E

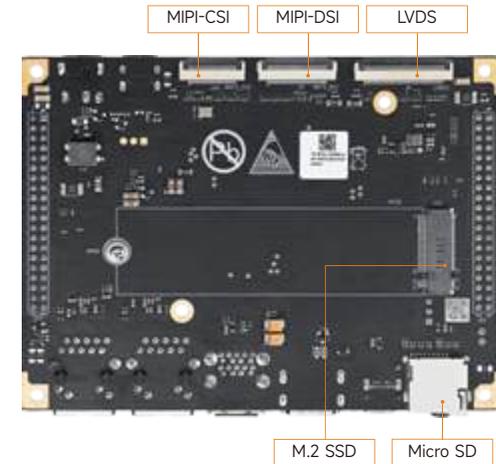
● **Peripherals/Interfaces**

Communications	2×RGMII, 2×USB2.0, 2×USB3.0, 2×PCIe3.0, PCIe2.1, SDIO, SATA3.0, 10×UART, 3×CAN, 4×SPI, 6×I2C, 16×PWM, 8×ADC
Multimedia	HDMI2.0a, eDP1.3, Dual MIPI-DSI_TX, Single LVDS, Parallel DSI, 2×MIPI CSI, Parallel CSI, 4×I2S/TDM, 8×ADC

● **Key Applications**



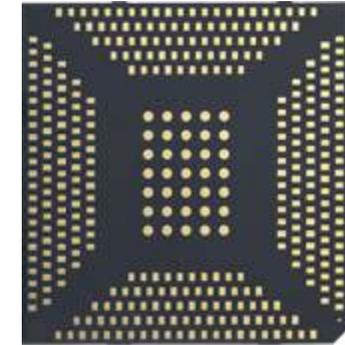
MYD-LR3568 Development Board Top-view



MYD-LR3568 Development Board Bottom-view

Rockchip | MYC-LR3576

- Rockchip RK3576 processor, 4x Cortex-A72@2.2GHz + 4x Cortex-A53@1.8GHz + Cortex-M0@400MHz
- LPDDR4X, eMMC, EEPROM
- Neural Processing Unit (NPU) Operating at Up to 6 TOPS, 3D GPU
- Supports Up to 4K@120fps High Frame Rate Video Decoding
- 43mm x 45mm; LGA Package, 381-pin; 0°C~+70°C Commercial or -40°C~+85°C Industrial
- Support Linux, Debian, Ubuntu, Android



• **Part Selections** (Other Configurations can be Customized for Mass Production)

SOM Part Number	CPU	CPU Cores and Clock Speed (Max)	RAM	ROM	Others	Package	Working Temp.	Dimensions	Software	Development Board Part Number
MYC-LR3576-32E4D-220-C	RK3576	4xCortex-A72@2.2GHz + 4xCortex-A53@1.8GHz + Cortex-M0@400MHz 6TOPS NPU	4GB LPDDR4X	32GB eMMC	32kbit EEPROM	LGA 381PIN	0°C~+70°C	43mm × 45mm	Linux Debian Ubuntu Android	MYD-LR3576-32E4D-220-C
MYC-LR3576-64E8D-220-C			8GB LPDDR4X	64GB eMMC						MYD-LR3576-64E8D-220-C
MYC-LR3576J-32E4D-160-I	RK3576J	4xCortex-A72@2.1GHz + 4xCortex-A53@1.9GHz + Cortex-M0@400MHz 6TOPS NPU	4GB LPDDR4X	32GB eMMC			-40°C~+85°C			MYD-LR3576J-32E4D-160-I-GK
MYC-LR3576J-64E8D-160-I			8GB LPDDR4X	64GB eMMC						MYD-LR3576J-64E8D-160-I-GK

• **Peripherals/Interfaces**

Communications	2×RGMII, USB/DP combo, PCIe2.1, SDIO, SATA3.0, 12×UART, 2×CAN FD, 5×SPI, 10×I2C, 10×I3C, DSMC/FlexBus
Multimedia	2×MIPI-CSI, DVP, HDMI, MIPI-DSI, 2×SPDIF TX, 2×SPDIF RX, 5×I2S
Others	8×SARADC

• **Key Applications**



Intelligent Healthcare



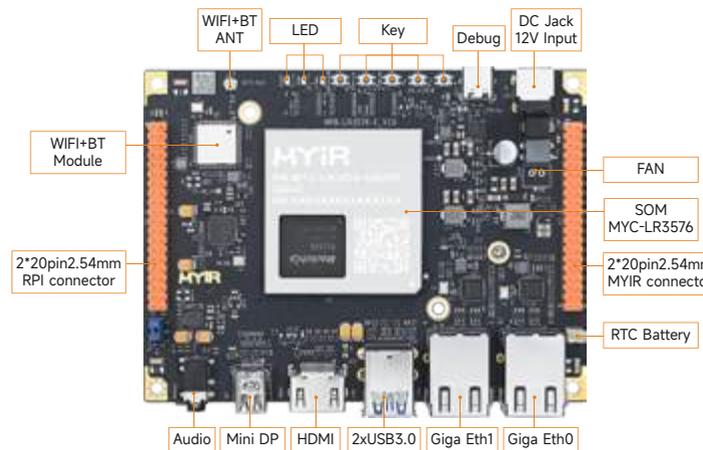
Automotive Electronics



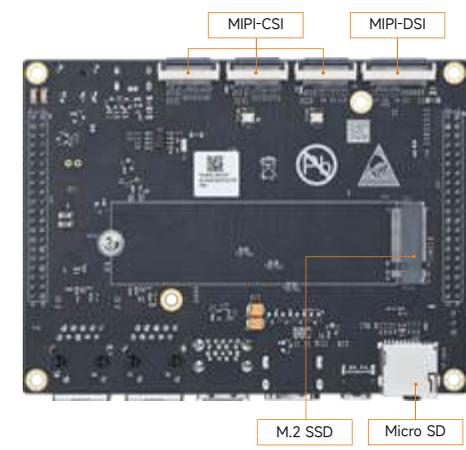
Industrial Manufacturing



Energy & Power



MYD-LR3576 Development Board Top-view



MYD-LR3576 Development Board Bottom-view

Solutions and Applications

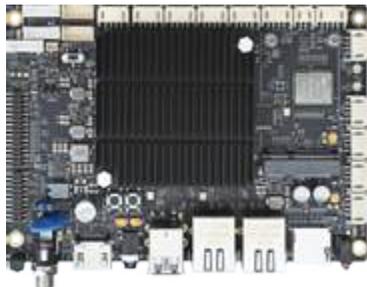
Single Board Computers

The embedded industrial single board computer is a complete computing system that integrates a processor, memory, storage, and various peripheral interfaces. It has gone through rigorous design and testing, exhibiting high stability and reliability, and can operate stably for long periods in harsh industrial environments. Engineers and developers can directly carry out application development and deployment on it, and it is widely used in fields such as industrial control, industrial automation, industrial data collection, medical equipment, and more.

Single Board Computers	CPU Vendor					 	
	ARM Cores						
A7 Single-core				MYS-6ULX P59 NXP i.MX6UL/i.MX6ULL A7@528MHz 10/100M ETH, USB2.0 HOST, USB2.0 OTG, LCD Module, Micro SD Card Slot			
A9 Single or Dual-core					Rico Board P61 TI AM437X A9@1.0GHz 1000M ETH, USB2.0 Host, Mini USB2.0, HDMI, LCD Module, Dual-Camera	Z-turn Board V2 P62 AMD-Xilinx XC7Z010/20 ARM: 2xA9@667MHz/766MHz FPGA: 28K/ 85K 1000M ETH, Mini USB2.0 OTG, CAN, UART, HDMI, TF Card	Z-turn Lite P63 AMD-Xilinx XC7Z010 ARM: 2xA9@667MHz FPGA: 28K 1000M ETH, Mini USB2.0 OTG, Debug UART, JTAG, TF Card
A53 Quad-core				MYS-8MMX-V2 P6 NXP i.MX 8M Mini 4xA53@1.8GHz+M4@400MHz 1000M ETH, 2x USB2.0 HOST, USB2.0 OTG, MIPI CSI, LVDS, HDMI, M.2 PCIe		FZ3 Card P64 Xilinx XCZU3EG ARM:4xA53@1.2GHz+2xR5@600MHz FPGA: 154K 1000M ETH, USB2.0, USB3.0 Host, TF, DP, PCIe, MIPI CSI, UART, JTAG	FZ5 Card P65 Xilinx XCZU5EV ARM:4xA53@1.2GHz+2xR5@600MHz FPGA: 256K 1000M ETH, 4xUSB3.0, RS232, RS485, CAN, TF, DP, HDMI, JTAG
A55 Dual or Octa-core		MYD-LT527-SX P57 Allwinner T527 8xA55@1.8GHz 2x1000M ETH, 6xUSB, 2xCAN, HDMI, MIPI DSI/CSI, WiFi/BT	Remi Pi P58 Renesas RZ/G2L 2xA55@1.2GHz+M33@200MHz 2x1000M ETH, 3xUSB2.0, WiFi/BT, MIPI CSI, LVDS, HDMI				

ALLWINNER | MYD-LT527-SX

- Allwinner T527 Processor, Up to 1.8GHz Octa-core ARM Cortex-A55 MPU with GPU
- 2GB LPDDR4, 16GB eMMC, 32Kbit EEPROM
- 2x RS232, RS485, USB 3.0, 5x USB 2.0, 2x CAN, TF Card Slot
- 2x Gigabit Ethernet, WiFi/Bluetooth, PCIe Slot for 4G/5G Module
- 2x MIPI-CSI, HDMI/Mini-DP/MIPI-DSI/LVDS, Audio Input/Output
- Supports for Android OS



MYD-LT527-SX Top-view



MYD-LT527-SX Bottom-view

Key Applications



Medical Device



Energy & Power



Vehicle Terminals



Edge Intelligent Boxes

Part Selections (Other Configurations can be Customized for Mass Production)

Part Number	CPU	CPU Cores and Clock Speed (Max)	RAM	ROM	Working Temp	Dimensions	Software
MYD-LT527M-16E2D-180-E-SX	T527M	4xCortex-A55@1.8GHz + 4xCortex-A55@1.4GHz RISC-V@200MHz	2GB LPDDR4	16GB eMMC	-20°C~+70°C	140mm x 100mm	Android

Features	Description
CPU	Allwinner T527 Processor, Up to 1.8GHz 8x Cortex-A55 MPU with GPU
RAM	2GB LPDDR4
ROM	16GB eMMC
Communications	1x Debug UART (TTL)
	1x RS485
	2x RS232
	2x TTL
	2x 10/100/1000M Ethernet
	1x USB2.0 Host (Type-A)
	1x USB3.0 Host (Type-A)
	4x USB2.0 Host (4-pin header connectors)
	1x Mini PCIe Interface for USB based 4G/5G Module
	1x SIM Card Slot
	1x Micro SD card slot
	2x CAN
	1x WiFi/BT Module
	1x IR RX Jack
Multimedia	1x HDMI Display Interface
	1x Dual-LVDS Display Interface
	1x eDP Display Interface
	1x MIPI-DSI Display Interface
	2x MIPI-CSI Camera Interface
	1x 3.5mm Headphone Jack
	1x MIC Interface
	1x Stereo Speaker Interface

RENESAS | Remi Pi

- RENESAS RZ/G2L Processor, 2x Cortex-A55@1.2GHz + Cortex-M33@200MHz
- 1GB DDR4, 8GB eMMC Flash, 32KB EEPROM
- 2x USB 2.0 HOST, 1x USB 2.0 OTG, 2x Gigabit Ethernet, WiFi/Bluetooth
- Camera Interface (MIPI-CSI), LVDS, HDMI, Audio Input/Output
- Optional 7-inch LCD Modules, Camera Module and RPI Module (RS232/RS485/CAN)
- Linux OS (Yocto based with QT / Debian / Ubuntu)



Remi Pi Top-view



Remi Pi Bottom-view

Features	Description
CPU	RENESAS RZ/G2L Processor, 2x Cortex-A55@1.2GHz + Cortex-M33@200MHz
RAM	1GB DDR4
ROM	8GB eMMC
Power Management	PMIC, RAA215300
Power Supply	USB Power Supply (Type-C)
WiFi/Bluetooth	2.4GHz/5GHz WIFI + BT4.2 Module
Ethernet	2x Gigabit Ethernet Interfaces
USB	1x USB 2.0 OTG (Type-C)
	2x USB 2.0 Host (Type-A)
Multimedia	1x HDMI Display Interface
	1x LVDS Display Interface
	1x MIPI-CSI Camera Interface
	1x Audio Input/Output Interface
Debug	2x Debug UART (Cortex-A55, Cortex-M33)
Buttons	ON/OFF, RESET, USER
Status LED	Power, System Status
RPI Interface	1x 2.54mm 2x 20-pin male expansion header (GPIO/I2C/UART/SPI/CAN)
RTC	Used for timing when power off

Key Applications



Industrial HMI



Medical Device



Industrial Control



Commercial Display

Part Selections (Other Configurations can be Customized for Mass Production)

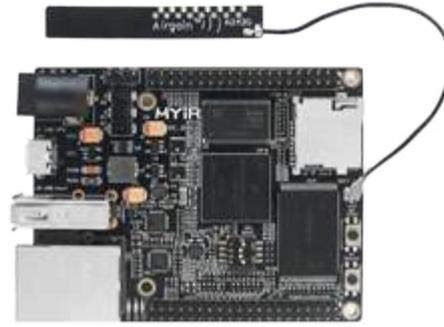
Part Number	CPU	CPU Cores and Clock Speed (Max)	RAM	ROM	Working Temp	Dimensions	Software
MYD-YG2L23-8E1D-120-C-REMI	R9A07G044L23GBG	2xCortex-A55@1.2GHz + Cortex-M33@200MHz	1GB DDR4	8GB eMMC	0°C~+70°C	120mm x 70mm	Linux Ubuntu Debian

NXP | MYS-6ULX

- NXP i.MX 6UL/i.MX 6ULL Processor, Cortex-A7@528MHz
- 256MB DDR3, 256MB Nand Flash
- 1x USB 2.0 HOST, 1x USB 2.0 OTG, 1x 10/100Mbps Ethernet
- Optional Expansion Board adds Ethernet, CAN, RS485, Audio, RTC and Camera
- Optional 4.3 or 7 inch LCD Module, Camera and WiFi Modules
- Linux OS (Yocto based with QT / Debian)



MYS-6ULX-IND



MYS-6ULX-IOT

Key Applications



Industrial HMI



Medical Device



Industrial Control



Energy & Power

Part Selections (Other Configurations can be Customized for Mass Production)

Part Number	CPU	CPU Cores and Clock Speed (Max)	RAM	ROM	Working Temp	Dimensions	Software
MYS-6ULX-IND	MCIMX6G2CVM05AB	Cortex-A7@528MHz	256MB DDR3	256MB Nand FLASH	-40°C~+85°C	70mm x 55mm	Linux
MYS-6ULX-IOT	MCIMX6Y2CVM05AB				0°C~+70°C		

Features	MYS-6ULX-IND	MYS-6ULX-IOT
Target Applications	Industry 4.0	IoT Applications
CPU	MCIMX6G2CVM05AA	MCIMX6Y2DVM05AA
RAM	256MB DDR3	
ROM	256MB Nand Flash	
USB	1x USB 2.0 OTG, 1x USB 2.0 Host	
Ethernet	1x 10/100M Ethernet Interface	
TF Card	1x Micro SD Card Slot	
Key	2x Keys	
Status LED	2x User LED	
Expansion Header	2x 2.0mm pitch 2x 20-pin Male Headers (1 x Ethernet, 8 x UARTs, 4 x I2C, 2 x CAN, 4 x SPI, 8 x ADC, 4 x PWM, 2 x I2S, 1 x 8-bit Camera, 1 x JTAG, up to 46 x GPIOs)	
LCD	24-bit RGB LCD & Touch Screen (50-pin FPC connector)	
WIFI	-	1x 2.4GHz, IEEE 802.11b/g/n Standards
Working Temp.	-40°C-85°C	0°C-70°C
OS	Linux (Yocto, Debian)	Linux (Yocto, Debian)

NXP | MYS-8MMX-V2

- NXP i.MX 8M Mini Processor, up to 4x Cortex-A53@1.8GHz + Cortex-M4@400MHz
- 2GB DDR4, 8GB eMMC Flash, 32MB QSPI FLASH
- 2x USB2.0 HOST, 1x USB2.0 OTG, Gigabit Ethernet, WiFi/Bluetooth, M.2 PCIe Interface
- Camera Interface (MIPI-CSI), LVDS, HDMI
- Supports Running Yocto Linux and Ubuntu OS



MYS-8MMX-V2 Top-view



MYS-8MMX-V2 Bottom-view

Key Applications



Medical Device



Energy & Power



Industrial Control



Intelligent Fire Systems

Part Selections (Other Configurations can be Customized for Mass Production)

Part Number	CPU	CPU Cores and Clock Speed (Max)	RAM	ROM	Working Temp	Dimensions	Software	Enclosure
MYS-8MMQ6-V2-8E2D-180-C	MIMX8MM6DVTLZAA	4xCortex-A53@1.8GHz + Cortex-M4@400MHz	2GB DDR4	8GB eMMC	0°C~+70°C	95mm x 69mm	Linux Ubuntu	Without
MYS-8MMQ6-V2-8E2D-180-C-B						135mm x 74.5mm x 35.8mm		With
MYS-8MMQ6-V2-8E2D-160-I	MIMX8MM6CVTKZAA	4xCortex-A53@1.6GHz + Cortex-M4@400MHz			-40°C~+85°C	95mm x 69mm		Without
MYS-8MMQ6-V2-8E2D-160-I-B						135mm x 74.5mm x 35.8mm		With

Features	Description
CPU	NXP i.MX 8M Mini, up to 4x Cortex-A53@1.8GHz + Cortex-M4@400MHz
RAM	2GB DDR4
ROM	8GB eMMC
Power Input	2 PIN Phoenix Connector
USB	1x USB 2.0 OTG (Type-C)
	2x USB 2.0 Host (Type-A)
Multimedia	1x HDMI Display Interface
	1x LVDS Display Interface
	1x MIPI-CSI Camera Interface
Ethernet	1x Gigabit Ethernet Interface
WiFi/Bluetooth	1x WIFI/BT Antenna SMA
RTC	1x 2PIN 1.25mm Pitch Connector
M.2	1x NVMe PCIe M.2 2242 SSD Slot
Expansion Interface	1x 2x25PIN 2.0mm Pitch Expansion Interface
Micro SD	1x Micro SD Card Slot
Debug	1x Debug UART, 3PIN 2.54mm Pitch
Buttons	ON/OFF, RESET, USER
Status LED	User, System Status

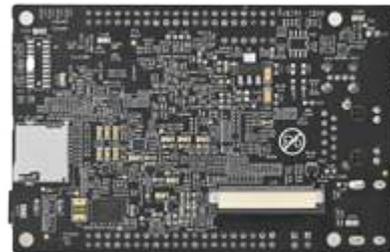


Rico Board

- Up to 1GHz TI AM437x Sitara ARM Cortex-A9 Processor
- 512MB DDR3 SDRAM, 4GB eMMC Flash, 16MB QSPI Flash, 32KB EEPROM
- UARTs, USB Host/Device, Gigabit Ethernet, Dual-Camera, TF, ...
- Supports HDMI and LCD Display
- Supports for Linux OS



Rico Board Top-view



Rico Board Bottom-view

Features	Description
CPU	Up to 1GHz TI AM437x Sitara ARM Cortex-A9 Processor
RAM	512MB DDR3
ROM	4GB eMMC, 16MB QSPI Flash, 32KB EEPROM
Display	24-bit true color display interface
USB	1x USB 2.0 Host port, 1x Mini USB 2.0 Device port
HDMI	1x HDMI Display interface
TF Card	1x TF card interface
Camera	2x Camera interfaces
Ethernet	1x Gigabit Ethernet Interface
UART	1x Debug UART
JTAG	1x 20-pin JTAG interface
Expansion Interface	2x SPI, 2x I2C, 2x CAN, 4x UARTs, 1x MMC, 8x ADC
PCB	8-layer design
Dimensions	65mm x 100mm
OS Support	Linux

Key Applications



Industrial HMI



Medical Device



Industrial Control



Scanner

Part Selections (Other Configurations can be Customized for Mass Production)

Part Number	CPU	CPU Cores and Clock Speed (Max)	RAM	ROM	Working Temp	Dimensions	Software	Accessories
MYS-4378-100-C	AM4378BZDN100	Cortex-A9@1.0GHz	512MB DDR3	4GB eMMC	0°C~+70°C	100mm x 65mm	Linux	With
MYS-4378-100-C-S								Without

AMD XILINX | Z-turn Board V2

- Xilinx XC7Z010/20 Processor, 2*Cortex-A9@667MHz+Artix 7 FPGA
- 1GB DDR3, 16MB QSPI Flash, 64Kbit EEPROM
- USB_UART, USB2.0 OTG, 1 x 10/100/1000Mbps Ethernet, CAN, HDMI, TF, ...
- Onboard Three-axis Acceleration Sensor and Temperature Sensor
- Supports Optional Camera Module and Z-turn IO Cape
- Ready-to-Run Linux Single Board Computer
- Supports Python Development



Z-turn Board V2 Top-view



Z-turn Board V2 Bottom-view

Features	Description
CPU	Xilinx XC7Z010/XCZ7020
RAM	1GB DDR3 SDRAM
ROM	16MB QSPI Flash
Sensor	Onboard Three-axis Acceleration Sensor, Temperature Sensor
USB	1x Mini USB2.0 OTG, 1 x USB-UART debug interface
HDMI	1x HDMI (supports 1080p resolution)
TF	1x TF card interface
CAN	1x CAN
Ethernet	1x 10/100/1000Mbps Ethernet Interface
User I/O	2x 1.27mm pitch 80-pin SMT female connectors PLIO: 90/106 (XC7Z010/XCZ7020)
Dimensions	63mm x 102mm x 1.6mm (8-layer PCB design)
OS support	Linux

Key Applications



Automotive



Medical Device



Industrial



Visual Monitoring

Part Selections (Other Configurations can be Customized for Mass Production)

Part Number	CPU	CPU Cores and Clock Speed (Max)	RAM	ROM	Working Temp	Dimensions	Software	Accessories
MYS-7Z010-V2-0E1D-667-C	XC7Z010-1CLG400	2xCortex-A9@667Hz + Atrix 7 FPGA (28K)	1GB DDR3	16MB QSPI Flash	0°C~+70°C	63mm × 102mm	Linux	With
MYS-7Z010-V2-0E1D-667-C-S								Without
MYS-7Z020-V2-0E1D-766-C	XC7Z020-2CLG400	2xCortex-A9@766Hz + Atrix 7 FPGA (85K)						With
MYS-7Z020-V2-0E1D-766-C-S								Without

AMD

XILINX | Z-turn Lite

- Xilinx XC7Z010 Processor, 2*Cortex-A9@667MHz+Artix 7 FPGA
- 512MB DDR3, 4GB eMMC, 16MB QSPI Flash
- USB2.0 OTG, 10/100/1000M Ethernet, TF, Debug UART, JTAG...
- One 120 Position Connector Socket for Expansion interface
- Ready-to-Run Linux Single Board Computer
- Optional Camera and LCD Modules, IO Extension Cape



Z-turn Lite Top-view



Z-turn Lite Bottom-view

Features	Description
CPU	Xilinx XC7Z010
RAM	512MB DDR3 SDRAM
ROM	4GB eMMC Flash, 16MB QSPI Flash
Ethernet	1x 10/100/1000Mbps Ethernet Interface
USB	1x Mini USB2.0 OTG
Input and Output	1x 2.54mm pitch 14-pin JTAG Interface
	1x 0.5mm pitch 120 Position Connector Socket for Expansion Interface
	1x 2.54mm pitch 4-pin Debug UART Interface
TF	1x TF card interface
Buttons	1x Reset, 1 x User
Dimensions	91mm x 63mm (10-layer PCB design)
OS support	Linux

Key Applications



Automotive



Medical Device



Industrial



Visual Monitoring

Part Selections (Other Configurations can be Customized for Mass Production)

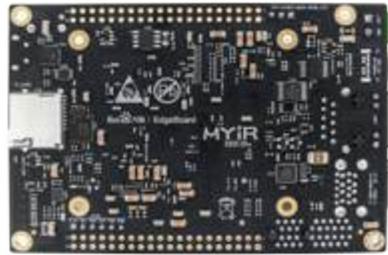
Part Number	CPU	CPU Cores and Clock Speed (Max)	RAM	ROM	Other Storage	Working Temp	Dimensions	Software	Accessories
MYS-7Z010-L-C	XC7Z010-1CLG400	2xCortex-A9@667Hz + Atrix 7 FPGA (28K)	512MB DDR3	4GB eMMC	16MB QSPI Flash	0°C~+70°C	91mm x 63mm	Linux	With
MYS-7Z010-L-C-S									Without

AMD XILINX | FZ3 Card

- Xilinx Zynq UltraScale+ ZU3EG MPSoC Processor, 4*Cortex-A53@1.2GHz+2*Cortex-R5@600MHz
- DDR4, eMMC, QSPI Flash, EEPROM
- USB2.0, USB3.0, Gigabit Ethernet, TF, DP, PCIe, MIPI-CSI, BT1120, USB-UART, JTAG...
- Computing Power up to 1.2TOPS, MobileNet up to 100FPS
- Ready-to-Run PetaLinux 2020.1
- Supports Xilinx Vitis Software Development Platform



FZ3 Card Top-view



FZ3 Card Bottom-view

Features	Description
CPU	XCZU3EG
RAM	4GB DDR4 (64-bit)
ROM	8GB eMMC
QSPI FLASH	32MB QSPI
EEPROM	32KB I2C EEPROM
PHY	1x Gigabit PHY
	2x USB 2.0 PHY
Mini DP	4K/30fps (2lane)
Ethernet	1x Gigabit Ethernet Interface
USB	1x USB 2.0 Host, 1x USB 3.0 Host
PCIe	PCIe 2.1 x 1 lane
MIPI	FPC_25PIN 4lane
BT1120	FPC_32PIN 16bit
Debug	1x Mini USB-to-UART Port
Expansion IOs	2x 2.54mm pitch 2 x 20-pin IO Expansion Interfaces
PCB	12-layer Design
Dimensions	100mm x 70mm

Key Applications



Security Monitoring



Industrial Quality Assurance



Medical Device



Artificial Intelligence (AI)

Part Selections (Other Configurations can be Customized for Mass Production)

Part Number	CPU	CPU Cores and Clock Speed (Max)	RAM	ROM	Working Temp	Other Storage	Software	Accessories
MYS-ZU3EG-8E4D-EDGE-K2	XCZU3EG-1SFVC784I	ARM: 4xA53@1200MHz + 2xR5@533MHz + UltraScale+ FPGA 154K	4GB DDR4	8GB eMMC	-40°C~+85°C	32MB QSPI FLASH 32Kbit EEPROM	Linux	With

AMD XILINX | FZ5 Card

- Zynq UltraScale+ XCZU5EV MPSoC, 4x Cortex-A53@1.2GHz + 2x Cortex-R5@600MHz+FPGA
- Computing Power up to 2.4TOPS, Runs at 55 FPS for ResNet-50
- 8GB DDR4, 32GB eMMC, 64MB QSPI Flash, 32KB EEPROM
- RS232, RS485, 4 x USB 3.0, Gigabit Ethernet, CAN, TF, DP, HDMI-IN, JTAG...
- Supports 8- to 16-channel Video Decoding and 4- to 8-channel Intelligent Analysis
- Ready-to-Run PetaLinux



FZ5 Card Top-view



FZ5 Card Bottom-view

Features	Description
CPU	XCZU5EV
RAM	8GB DDR4 (64bit, 2400MHz)
ROM	32GB eMMC
QSPI FLASH	64MB QSPI
EEPROM	32KB EEPROM
Serial Ports	1x RS232, 1x RS485, 1 x USB-UART Debug
Ethernet	1x Gigabit Ethernet
USB3.0	4x USB3.0 Host
CAN	1x CAN
HDMI	1x HDMI In
MIPI DP	1x Mini DisplayPort (DP), 4K/30fps
User I/O	1x FPC_40PIN (Reserved for MIPI-CSI)
	1x 1.27mm pitch 2 x 50-pin IO Expansion Interface (5 x PS_MIO, 69 x PL_IO)

Key Applications



Intelligent Security



Medical Diagnosis



Artificial Intelligence (AI)



Consumer Electronics

Part Selections (Other Configurations can be Customized for Mass Production)

Part Number	CPU	CPU Cores and Clock Speed (Max)	RAM	ROM	Working Temp	Other Storage	Software
MYS-ZU5EV-32E8D-EDGE-BOX	XCZU5EV-2SFVC784I	4xCortex-A53@1.5GHz + 2xCortex-R5@600MHz	8GB DDR4	32GB eMMC	-40°C~+70°C	32KB EEPROM	PetaLinux

Solutions and Applications

Industrial Personal Computers (IPCs)

The Industrial Personal Computer (IPC) is an embedded computer specially designed for industrial control applications. It adopts an integrated design, integrating the single board computer, communication module, components, and housing into a single device. The entire unit features anti-interference, resistance to high and low temperature, dustproof and waterproof, and long time and stable operation, etc. It is widely used in industrial automation, instrumentation testing, data acquisition, the Internet of Things, intelligent transportation, energy management, medical equipment, rail transportation, and other fields.

- ▶ MYD-LR3568-GK-B P67
- ▶ MYD-LR3576-B P68
- ▶ MYS-8MMX-V2 Box P69
- ▶ FZ5 EdgeBoard AI Box P70
- ▶ MY-EVC700S-V2 P71
- ▶ MYD-LT527-GK-B P72

Rockchip | MYD-LR3568-GK-B

- Rockchip RK3568 Application Processor based on Up to 1.8GHz Quad ARM Cortex-A55 Cores
- LPDDR4, eMMC, EEPROM
- 2x USB 3.0, 3x USB 2.0, 2x CAN, RS232, 2x RS485, Debug (USB-UART), Micro SD Card Slot
- 2x Gigabit Ethernet, WiFi/Bluetooth, PCIe Slot for 4G Module
- Supports Mini-DP and HDMI for High-resolution Displays, along with Audio Input/Output Interface
- Support Linux, Debian, Ubuntu, Android



MYD-LR3568-GK-B Front-view



MYD-LR3568-GK-B Back-view

Key Applications



Industrial Personal Computer



Multi-screen HD Player



Power Measurement & Control Terminal



Data Acquisition

Part Selections (Other Configurations can be Customized for Mass Production)

Part Number	CPU	CPU Cores and Clock Speed (Max)	RAM	ROM	Working Temp	Dimensions	Software
MYD-LR3568J-16E2D-180-I-GK-B	RK3568J	4xCortex-A55, up to 1.8GHz	2GB LPDDR4	16GB eMMC	-40°C~+85°C	160mm x 93.5mm x 44mm (with mounting bracket)	Linux Debian
MYD-LR3568J-32E4D-180-I-GK-B			4GB LPDDR4	32GB eMMC			

Features	Description
CPU	Rockchip RK3568 Processor, Up to 1.8GHz Quad ARM Cortex-A55 Cores
RAM	2GB/4GB LPDDR4
ROM	16GB/32GB eMMC
EEPROM	32KB EEPROM
Communications	1x USB-UART Debug Interface
	1x RS232
	2x RS485
	2x USB 3.0 Host Ports
	3x USB 2.0 Host Ports
	2x 10/100/1000Mbps Ethernet Interfaces
	2x CAN
	WiFi/Bluetooth Module
	1x WiFi/BT antenna interface
	1x M.2 Socket for a USB-based 4G LTE Module
Multimedia	1x SIM card holder
	1x HDMI 2.0 Interface
	1x Mini DisplayPort (DP) Output Interface
	1x 3.5mm Headphone/Mic Audio Jack

Rockchip | MYD-LR3576-B

- Rockchip RK3576 Octa-core Arm Processor with Quad Cortex-A72 Cores at 2.2 GHz and Quad Cortex-A53 Cores at 1.8 GHz
- LPDDR4X, eMMC, EEPROM
- Up to 6 TOPs NPU, 3D GPU, 4K Video Codec
- 2x USB 3.0, 2x Gigabit Ethernet, WiFi/BT, Debug (USB-UART), Micro SD Card Slot
- Supports Mini-DP and HDMI for High-resolution Displays, along with Audio Input/Output Interface
- Support Linux, Debian, Ubuntu, Android



MYD-LR3576-B Box Front-view



MYD-LR3576-B Box Back-view

Features	Description
POWER	12VDC 5.08 Phoenix Terminal
Debug	1x USB2.0 Type-C (Internal USB to TTL DEBUG)
KEY	1x RST Reset, 1x USER
SSD	1x M.2 2280 NVME SSD
SD	1x Micro SD card slot
Ethernet	2x 10/100/1000 Mbps Ethernet, RJ45
WiFi/Bluetooth	WiFi Module, supports 802.11a/b/g/n/AC+BT 5.2
4G/5G	Onboard MiniPCIE slot, SIM card slot, supports 4G/5G Module
USB	2x USB 3.0
	3x USB 2.0
UART	2x RS485
	1x RS232
CAN	2x CAN
Display	1x HDMI
	1x Mini-DP
Audio	1x 3.5mm Headphone/Mic Audio Jack

Key Applications



Integrated Gateway



Industrial Control



Power Intelligent Equipment



Edge Computing

Part Selections (Other Configurations can be Customized for Mass Production)

Part Number	CPU	CPU Cores and Clock Speed (Max)	RAM	ROM	Working Temp	Dimensions	Software
MYD-LR3576-64E8D-220-C-B	RK3576	4xCortex-A72@2.2GHz + 4xCortex-A53@1.8GHz + Cortex-M0@400MHz, 6TOPS NPU	8GB LPDDR4X	64GB eMMC	0°C~+70°C	170mm x 93.5mm x 34.5mm	Linux Debian Android

NXP | MYS-8MMX-V2 Box

- NXP i.MX 8M Mini Processor, up to 1.8 GHz Arm Cortex-A53 and 400MHz Cortex-M4 Cores
- 2GB DDR4, 8GB eMMC Flash, 32MB QSPI Flash
- 2x USB Host, 1x USB Type-C, 1x Gigabit Ethernet, WiFi/Bluetooth, Micro SD Card Slot, HDMI
- Supports Running Yocto Linux and Ubuntu OS



MYS-8MMX-V2 Box Front-view

MYS-8MMX-V2 Box Back-view

Features	Description
CPU	NXP i.MX 8M Mini, up to 4x Cortex-A53@1.8GHz + Cortex-M4@400MHz
RAM	2GB DDR4 (supports up to 4GB)
Storage	8GB eMMC (supports up to 128GB)
	32MB QSPI Flash
	1x Micro SD card slot
Power Supply	5V/2A (Power Input Interface: 2-pin phoenix connector)
Dimensions	135mm (L, including ears) x 74.5mm (W) x 35.8mm (H)
Working Temperature	0~+70°C (commercial grade)
	-40~+85°C (industrial grade)
Debug UART	1x Debug serial port (UART2, TTL, 3-pin 2.54mm pitch pin headers)
Ethernet	1x 10/100/1000 Mbps Ethernet
USB	1x USB 2.0 OTG (Type-C)
	2x USB 2.0 Host (Type-A)
WiFi/Bluetooth	1x 2.4G/5G Dual-Band WiFi and Bluetooth 5.0 Module (AP6256)
Antenna	1x Antenna interface for WiFi/BT Module
Display	1x HDMI output interface (support 1080p@60fps resolution)
LED	1x LED (System indicator - Green)

Key Applications



Medical Equipment



Industrial Gateway



Industrial Control



Industrial HMI

Part Selections (Other Configurations can be Customized for Mass Production)

Part Number	CPU	CPU Cores and Clock Speed (Max)	RAM	ROM	Working Temp	Dimensions	Software
MYS-8MMQ6-V2-8E2D-180-C-B	MIMX8MM6DVTLZAA	4xCortex-A53@1.8GHz + Cortex-M4@400MHz	2GB DDR4	8GB eMMC	0°C~+70°C	135mm x 74.5mm x 35.8mm	Linux Ubuntu
MYS-8MMQ6-V2-8E2D-160-I-B	MIMX8MM6CVTKZAA	4xCortex-A53@1.6GHz + Cortex-M4@400MHz			-40°C~+85°C		



FZ5 EdgeBoard AI Box

- AMD/Xilinx Zynq UltraScale+ ZU5EV MPSoC based on 1.5 GHz Quad Arm Cortex-A53 and 600MHz Dual Cortex-R5 Cores
- 8GB DDR4 (64-bit, 2400MHz), 32GB eMMC, 64MB QSPI Flash, 32KB EEPROM
- 4x USB 3.0, Gigabit Ethernet, RS232, RS485, CAN, Micro-SD, Mini DP, HDMI-IN, Debug ...
- Computing Power up to 2.4TOPS, Runs at 55 FPS for ResNet-50
- Supports 8 to 16 channels of video decoding and 4 to 8 channels of intelligent Analytics
- Supports Running PetaLinux



FZ5 EdgeBoard AI Box Front-view



FZ5 EdgeBoard AI Box Back-view

Key Applications



Intelligent Security



Medical Diagnosis



Artificial Intelligence (AI)



Consumer Electronics

Part Selections (Other Configurations can be Customized for Mass Production)

Part Number	CPU	CPU Cores and Clock Speed (Max)	RAM	ROM	Working Temp	Other Storage	Software
MYS-ZU5EV-32E8D-EDGE-BOX	XCZU5EV-2SFVC784I	4xCortex-A53@1.5GHz + 2xCortex-R5@600MHz	8GB DDR4	32GB eMMC	-40°C~+70°C	64MB QSPI Flash 32KB EEPROM	PetaLinux

Features	Description
CPU	Xilinx Zynq UltraScale+ XCZU5EV-2SFVC784I (784 Pin Package)MPSoC
RAM	8GB DDR4 (64-bit, 2400MHz)
Storage	32GB eMMC + 64MB QSPI Flash + 32KB EEPROM, 1x Micro SD card slot
Power Supply	DC 12V/3A
Dimensions	Body: 120mm x 100mm x 50mm, Hanger: 148mm x 100mm
Working Temperature	-40~+70°C
Working Humidity	20% ~ 90%, non-condensing
Serial Ports	1x USB-to-UART Port, 1x RS232, 1x RS485
Ethernet	1x 10/100/1000 Mbps Ethernet
USB	4x USB 3.0 Host
CAN	1x CAN Interface
Display	1x HDMI In port, 1x Mini DisplayPort 4K/30fps, 1x FPC_40PIN (MIPI-CSI)
User I/O	1x 1.27mm pitch 2 x 50-pin IO Expansion Interface (5 x PS_MIO, 69 x PL_IO)
Buttons	1x System Reset Button
LEDs	1x Red Power LED, 1x Green Status LED
RTC	1x 3V Rechargeable RTC Battery Interface (battery is not soldered by default, Model MS621T is recommended) 1x 1.5V Non-Rechargeable RTC Battery Holder (battery is not provided by default, Model AG3 or LR41 is recommended)
Software	Supports PetaLinux

ALLWINNER | MY-EVC700S-V2

- Allwinner T113-i, Up to 1.2GHz Dual-core ARM Cortex-A7 MPU with Single-core HiFi4 DSP
- 512MB DDR3, 4GB eMMC, 32KB EEPROM
- Debug UART, 2x RS232, 2x RS485, 2x USB Host, 2x CAN, TF Card Slot, Digital Input/Output
- 1x 10/100Mbps Ethernet, WiFi/Bluetooth, 4G LTE Module (Quectel EC200MCNLF-I03-MN0CA)
- LVDS Display Interface, Audio
- Supports Linux OS
- Supports Working Temperature Ranging from -40°C to 85°C



MY-EVC700S-V2 Front-view



MY-EVC700S-V2 Back-view

Key Applications



Universal Gateway



Smart Power Gateway



Data Acquisition

Part Selections (Other Configurations can be Customized for Mass Production)

Part Number	CPU	CPU Cores and Clock Speed (Max)	RAM	ROM	Working Temp	Dimensions	Software
MY-EVC700S-V2	T113-i	2xCortex-A7@1.2G	512MB DDR3	4GB eMMC	-40°C~+85°C	194mm×158mm×32.5mm	Linux OS

Features	Description
CPU	Allwinner T113-i Processor, Up to 1.2GHz Dual ARM Cortex-A7 Cores
Memory	512MB DDR3
Storage	4GB eMMC
	32KB EEPROM
	1x Micro SD card slot
Dimensions	194mm×158mm×32.5mm
Working Temperature	-40°C ~+85°C
Power supply	Rated power: ≥ 15W;
	Rated voltage: DC12V, Input range DC9V-15V
Communication Interfaces	2x USB 2.0 Host
	1x 10/100Mbps Ethernet interface (RJ45)
	WiFi/Bluetooth Module
	USB based 4G LTE Module (Quectel EC200MCNLF-I03-MN0CA)
	2x Antennas Interfaces(one for WiFi/BT and one for 4G)
	2x RS232
	2x isolated RS485
	2x isolated CAN
	2x DI
	2x DO

ALLWINNER | MYD-LT527-GK-B

- Allwinner T527 Processor based on up to 1.8GHz Octa-core ARM Cortex-A55
- Up to 2 TOPs NPU, G57 MC1 GPU
- 4GB LPDDR4, 32GB eMMC, 32Kbit EEPROM
- 1x USB 3.0, 4x USB 2.0, 2x CAN, RS232, 2x RS485, Micro SD Card Slot
- 2x Gigabit Ethernet, WiFi/Bluetooth, PCIe Slot for 4G Module
- Supports Mini-DP and HDMI for High-resolution Displays, along with Audio Input/Output Interface
- Supports Linux and Ubuntu OS



MYD-LT527-GK-B Box Front-view



MYD-LT527-GK-B Box Back-view

Key Applications



Industrial Computers



Gateway



Edge Computing

Part Selections (Other Configurations can be Customized for Mass Production)

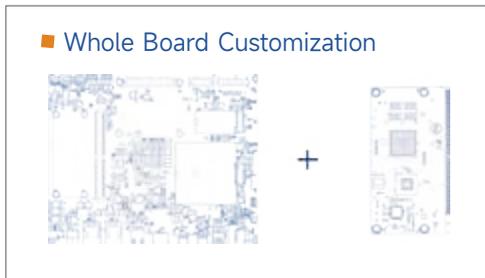
Part Number	CPU	CPU Cores and Clock Speed (Max)	RAM	ROM	Working Temp	Dimensions	Software
MYD-LT527M-16E2D-180-I-GK-B (without NPU)	T527M02X0DCH	8xCortex-A55, up to 1.8GHz	2GB LPDDR4	16GB eMMC	-40°C~+85°C	130mm x 93.5mm x 44mm (without mounting bracket)	Linux Ubuntu OS
MYD-LT527MN-32E4D-180-I-GK-B (with NPU)			4GB LPDDR4	32GB eMMC		160mm x 93.5mm x 44mm (with mounting bracket)	

Features	Description
CPU	Allwinner T527, up to 8*Cortex-A55@1.8GHz
Memory	4GB LPDDR4
Storage	32GB eMMC, 32Kbit EEPROM
	1x Micro SD card slot
Power Supply	12VDC±20% 2A (Phoenix terminal)
Dimensions	130mm(160mm with mounting bracket) x 93.5mm x 44mm
Working Temperature	-40~+85°C (WiFi/BT Module: -30-85 Celsius)
Serial Ports	1x RS232, 2x RS485
Net	2x 10/100/1000 Mbps Ethernet, WiFi/Bluetooth Module
	1x WiFi/BT antenna interface
	1x M.2 Socket for a 4G LTE Module (4G LTE Module is not provided) 1x SIM card holder
USB	1x USB 3.0 Host (Top 1x2 Type-A Host), 4x USB 2.0 Host
CAN	2x CAN Interfaces
Display	1x HDMI 2.0 Interface (Supports 1920x1080@60Hz by default)
	1x Mini DisplayPort (DP) Output Interface (Supports 2.5K@60Hz by default)
Audio	1x 3.5mm Headphone/Mic Audio Jack
Others	2x Buttons (1x Reset Button, 1x User Button)
	2x LEDs (1x RUN Status LED, 1x ERR User LED)

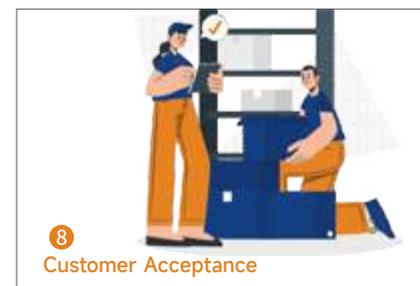
ODM Services

Based on years of experience in the embedded industry, MYiR has amassed extensive product technology and project development expertise in embedded software and hardware development utilizing ARM/FPGA core processors. MYiR also offers professional and efficient customized services tailored to the specific requirements of customers.

Customized Solutions



Customized Service Process



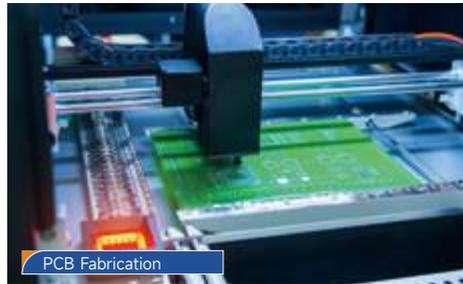
OEM Services

MYiR's Smart SMT factory is committed to providing customers with one-stop PCBA manufacturing services, encompassing PCB manufacturing, component procurement, SMT processing, assembly, and testing. Located in Longhua District, Shenzhen, the factory utilizes its advanced production equipment and management system, rigorous quality control procedures, comprehensive supply chain system, and robust engineering support to assist customers in enhancing production efficiency, reducing product delivery time, and ensuring production quality. It caters to a diverse range of customers across various industries, including industrial control, power communication, new energy, automotive electronics, medical electronics, smart home, security, and numerous other sectors globally.

One-stop PCBA Manufacturing Service



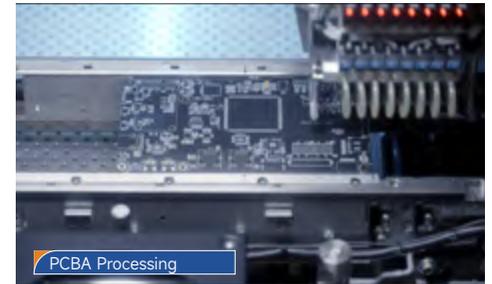
DFM (Design for Manufacturing)



PCB Fabrication



Parts Sourcing



PCBA Processing



Program Burning and Testing



High Temperature Aging Test



Conformal Coating



Finished Product Assembly

OEM Services Cover Many Industries



Industrial Control



Power Communication



New Energy



Automotive Electronics



Medical Instruments



Intelligent Security



Engineering Machinery



Rail Transit



Industrial Gateway



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